

# DIGMAPS: a standalone tool to study digitization

an overview of a digitizer strategy for CMOS/MAPS sensors

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thanks to A.Geromitsos and J.Baudot

- Motivations for a CMOS sensor digitizer, task list.
- DIGMAPS: presentation of the tool. Example.
- Summary and outlook

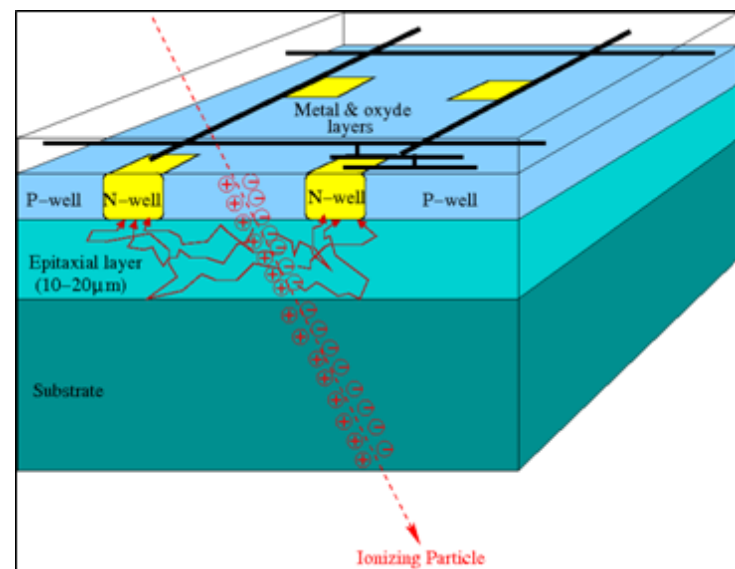
# Why a digitizer tool for MAPS ?

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- 2 mains motivations
  - Being able to foresee the response of a future chips
    - Help to optimize a design for a given application, e.g.  
N bits of ADCs, Discriminator thresholds, occupancy, hit separation, Pitch, number of layers, zero suppression stage, etc.
  - Test model for simulation
    - Goal: being able to provide models/algorithms easily transportable in real experiment  
e.g. fast or full simulation for STAR-HFT
    - Other experiments/projects will/may need also a digitizer  
CBM, AIDA, ILC, ALICE upgrade, superB, etc.
- 1 local long term goal
  - Get a full simulation chain for alignment studies
    - AIDA project (European project « Advanced Infrastructures for Detectors and Accelerators)
    - W.P.9.3: Build a telescope + target + vertex detector sector
    - Geant 4 + digitizer + tracking/alignement/vertexing
- 1 road map
  - Build a data driven model
    - to take advantage of our knowledge coming from ~30 beam test campaigns
    - Because a pure realistic analytical model is difficult to build

# What do we want to simulate ?

- Step 1: incident particle generation
  - Nature, energy spectrum, incident angle spectrum
    - Beam test, beamstrahlung spectrum for ILC, etc.
- Step 2: energy deposition  $\Rightarrow$  charge generation
  - Landau law (MPV = 80 e<sup>-</sup> /  $\mu\text{m}$ )
- Step 3: charge transport up to the N-well diodes
  - Thermal diffusion  $\neq$  depleted detectors
  - Charge sharing between pixels enhanced
  - Recombination, charge collection efficiency
  - Reflexion at the epi/substrate interface
  - Noise, fake pixels
- Step 4: digital part
  - Discriminator / ADC dynamic range
    - FPN, temporal noise.
  - Zero suppression stage
- Step 5: clustering algorithms
  - Resolution, hit separation
- Step 6: (not included) tracking, vertexing etc.



- Test Criteria:
  - Realistic performances
    - Efficiency,
    - resolution,
    - fake rate
  - Charge sharing
    - occupancy (multiplicity)
    - Hit separation

# DIGMAPS: a standalone digitizer tool

- MAPS Digitizer (DIGMAPS)

- From particle generation
- To the digitizer

- Library running in root

- Easy to load
- Easy to run

```
{
  gROOT->ProcessLine(".L digaction.cxx");
  gROOT->ProcessLine(".L digadc.cxx");
  gROOT->ProcessLine(".L digbeam.cxx");
  gROOT->ProcessLine(".L digplane.cxx");
  gROOT->ProcessLine(".L digparticle.cxx");
  gROOT->ProcessLine(".L digreadoutmap.cxx");
  gROOT->ProcessLine(".L digcluster.cxx");
  gROOT->ProcessLine(".L digevent.cxx");
  gROOT->ProcessLine(".L diginitialize.cxx");
  gROOT->ProcessLine(".L dighistograms.cxx");
  gROOT->ProcessLine(".L digmaps.cxx");
  // gROOT->ProcessLine(".L digproto.cxx");
}
```

```
DIGMAPS myDIGMAPS("name","title", "~/mydircode/", "input.txt", "~/myoutputdir", "output.txt", "foresee")
```

- All output stored in Root format

➤ .x Read.C ; .x Plot.C

```
Int_t myconfig = 1;
myDIGMAPS2.PrintConfigurations();
myDIGMAPS2.PlotAConfiguration(myconfig, 1);
```

- Input data cards to compare any configurations

```

This is a Configuration File for Silicon Tracking Analysis DIGMAPS Package
created -> 18/03/2011
Author = Auguste Besson abesson@in2p3.fr
-----
!!!! DO NOT USE Colons in Comments !!!
-----
Action Parameter
chose the action -> foresee = model result ; train = adjust/fit
plot = fill histograms from the tree.
//Doit "foresee"
Model: "basic"

-----
// BEAM Parameter
RunNumber: 1000
NumberOfEvents: 10000
// Beam generation option.
// 1=realistic beam with random number of particle per event
// 2=1 particle per event with a hit in a central pixel
BeamOption: 2
//number of particles per mm^2 on the Plane per event (Lambda factor)
ParticleDensity: 5.0
// ParticleDensityWidth 0.5
// incident angle in degrees in cylindrical coordinates (theta and phi)
Angles: 3
ThetaIncidentDeg 0.0 10.0 20.0
PhiIncidentDeg 0.0 0.0 45.0

// PLANE Parameters
-----GENERAL GEOMETRY
//---pixel pitch in X and Y in microns
Ngeom: 4
PitchX: 10.00 20.00 30.00 40.00
PitchY: 10.00 20.00 30.00 40.00
//---Noise in electrons
NoiseElectrons: 10.85 9.20 9.40 9.80
//---epitaxial thickness in microns
EpitaxialThickness: 12.65 10.80 8.69 7.78

//-----OTHER PARAMETERS
//---number of pixels
NpixelsX: 21
NpixelsY: 21
//---Chip temperature
NTemperature: 1
Temperature: 10
//-----CHARGE TRANSPORT
//---ionization energy (eV)
IonizationEnergy: 3.6
//---Starting Segment size (in microns)
SegmentSize: 0.1
//---Maximum Segment size (in microns)
MaximumSegmentSize: 1.0
//---Maximum Charge Per Segment (in electrons)
MaximumChargePerSegment: 1.0
//---Diffusion Maximum Range in X and Y (in pitch units)
DiffusionMaximumRangeInX: 2.5
DiffusionMaximumRangeInY: 2.5
//---Reflexion Coefficient on the subtrat-epi border (1.0 means 100%) NOT USED
ReflexionCoefficient: 1.0

```

```

-----CHARGE TRANSPORT MODEL
//---basic model
//---sigma of the gaussian width dispersion of charge at 10 microns depth
BasicModel_SigmaTenMicrons: 10.0
//---Chose Model (1=Lorentz2D , 2=Gauss2D)
ChargeModel: 2
//---Lorentz2D model
//---C term of the Lorentz width dispersion
Lorentz2DModel_Cp0: 0.6607
Lorentz2DModel_Cp1: 0.40 //0.400664
Lorentz2DModel_RangeLimit_InPitchUnit: 2.5
//---Gauss2D Model
//sum of 2d gaussian The sigma are lineary dependant to the pitch
Gauss2DModel_signal_Cp0: 1.12
Gauss2DModel_signal_Cp1: 0.35
Gauss2DModel_sigma2_Cp0: 1.16
Gauss2DModel_sigma2_Cp1: 0.83
Gauss2DModel_weight: 0.34

// ADC Parameters
// number of different ADC to test
NADC: 3
// ADC parameters
Nbits = number of bits of the ADC. There will be (2^Nbits - 1) thresholds.
LSB, Electron_Conversion and ADC_thresholds are in Noise multiple units (e.g. 2.0 = 2.0 * Noise)
There are 2 different ways to set the ADC
EITHER
1/ ADC_linear = 1 (the response is linear, so setting the LSB and
the Electron Conversion factor allow to compute all thresholds.
= thresholds will be = LSB, LSB+1xElectron_conversion, LSB+2xElectron_conversion etc.
LSB= 1.5 = threshold of the first significant bit
Electron_Conversion= 1.5
ADC_thresholds= -
OR
2/ ADC_linear = 0 (the response is not linear, so enter all the different threshold values
LSB= -
Electron_Conversion= -
ADC_thresholds= 2.0 4.0 5.0 etc.

---ADC 1
Nbits: 1
ADC_linear: 0
LSB: -
Electron_Conversion: -
ADC_thresholds: 5.0
---ADC 2
Nbits: 12
ADC_linear: 1
LSB: 0.64
Electron_Conversion: 0.64
ADC_thresholds: -
---ADC 3
Nbits: 12
ADC_linear: 1
LSB: 0.60
Electron_Conversion: 0.60
ADC_thresholds: -

```

- Many input parameters:
  - Beam (flux, angle)
  - MAPS (pitch, noise, epi. Layer)
  - Charge transport Model
  - ADC/discr threshold
  - Etc.

(under developpment)



ROOT

```

//create the file, the tree and a
TFile f("tree.root","create");
TTree t("t","A simple tree with 3
t.Branch("px","px","D/F");
t.Branch("py","py","D/F");

```

Quick Links:	ROOT Homepage	Class Index	Class Hierarchy	Search documentation...	Search
Source:	header file	source file	Inheritance tree (.pdf)	viewVC header	viewVC source
Sections:	class description	function members	data members	class charts	

(UNKNOWN PRODUCT) » CODE » DIGParticle

## class DIGParticle: public TObject

```

Double_t DIGParticle::Lorentz2D(Double_t *w, Double_t *par){

```

### Function Members (Methods)

```

public:
    DIGParticle ()
    DIGParticle (DIGParticle& adigparticle)
    DIGParticle (Float_t EntryX, Float_t EntryY, Float_t EntryZ, Float_t Energy_deposited)
    virtual ~DIGParticle ()
    void AddPixel (Float_t AnalogCharge, Int_t PixelNumber)
    void AddRandomNoise (DIGPlane* myDIGPlane)
    void AnalogToDigitalconversion (DIGADC* myDIGADC)
static TClass* Class ()
    virtual void Clear (Option_t* = "")
    void ComputeChargeDeposition (Float_t StartingSegmentSize, Float_t MaximumChargePerSegment, Float_t MaximumSegmentSize)
    void ComputeChargeTransport (DIGPlane* myDIGPlane)
    Double_t GaussianLaw (Double_t mean, Double_t sigma)
vector<Float_t> GetAnalogCharge ()
vector<Int_t> GetDigitalCharge ()
    Float_t GetEnergy_deposited ()
    Float_t GetEntryX ()
    Float_t GetEntryY ()
    Float_t GetEntryZ ()
    Float_t GetExitX ()
    Float_t GetExitY ()
    Float_t GetExitZ ()
    Int_t GetNpixels ()
    Int_t GetNSegment ()
vector<Int_t> GetPixelMap ()
    Int_t GetPixelNumber (DIGPlane* myDIGPlane)
vector<Float_t> GetSegmentCharge ()
vector<Float_t> GetSegmentX ()
vector<Float_t> GetSegmentY ()

```

```

179 }
180 //
181 //
182 void DIGParticle::ComputeChargeDeposition(Float_t StartingSegmentSize, Float_t MaximumSegmentSize,
183                                          Float_t MaximumChargePerSegment)
184 {
185     Float_t SegmentSize = StartingSegmentSize;
186     Float_t TotalLength = TMath::Sqrt((fExitX-fEntryX)*(fExitX-fEntryX)
187                                     +(fExitY-fEntryY)*(fExitY-fEntryY)
188                                     +(fExitZ-fEntryZ)*(fExitZ-fEntryZ));
189
190     Float_t ChargePerSegment = 0.0;
191     if(SegmentSize<0.0){
192         SegmentSize=0.001;
193     }
194     fNSegment = int(TotalLength*1.000001/SegmentSize) ;
195     if(fNSegment<1){
196         fNSegment=1;
197     }
198     SegmentSize = TotalLength/float(fNSegment);
199     ChargePerSegment = fEnergy_deposited / float(fNSegment);
200
201     while((SegmentSize>MaximumSegmentSize)&&(ChargePerSegment > MaximumChargePerSegment)){
202         Int_t newNSegment = int(fNSegment *1.1);
203         if(newNSegment==fNSegment){fNSegment++;}
204         SegmentSize = TotalLength/float(fNSegment);
205         ChargePerSegment = fEnergy_deposited / float(fNSegment);
206     }
207     Float_t xstep = fExitX-fEntryX;
208     Float_t ystep = fExitY-fEntryY;
209     Float_t zstep = fExitZ-fEntryZ;
210
211     for (Int_t i=0 ; i<fNSegment ; i++){
212         fSegmentX.push_back(fEntryX + (float(i+0.5)* xstep/float(fNSegment)) );
213         fSegmentY.push_back(fEntryY + (float(i+0.5)* ystep/float(fNSegment)) );
214         fSegmentZ.push_back(fEntryZ + (float(i+0.5)* zstep/float(fNSegment)) );
215         fSegmentCharge.push_back(ChargePerSegment) ;
216     }
217 }
218
219
220 }
221 //
222 //
223

```

Quick Links: ROOT Homepage Class Index  
(UNKNOWN PRODUCT)

### Class Index

Modules  
CODE

Jump to  
D DIGAc DIGB DIGC DIGE DIGH DIGI  
DIGM DIGP DIGPI DIGR

- DIGADC
- DIGAction
- DIGBeam
- DIGCluster
- DIGEvent
- DIGHistograms
- DIGInitialize
- DIGInitialize::ADCPParameter\_t
- DIGInitialize::ActionParameter\_t
- DIGInitialize::BeamParameter\_t
- DIGInitialize::PlaneParameter\_t
- DIGMAPS
- DIGParticle
- DIGPlane
- DIGReadoutmap

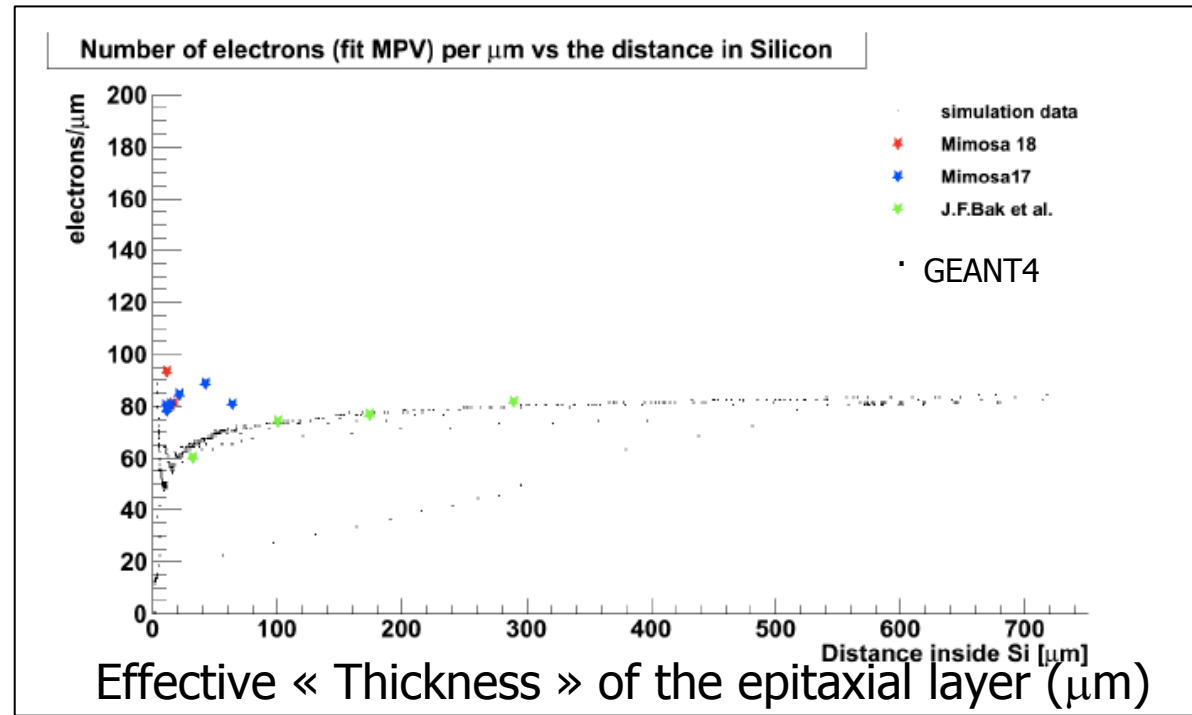
> Last changed: 2011-09-01 17:06 > Last generated: 2011-09-01  
This page has been automatically generated. For comments or suggestions

# Step 2: Energy deposition

- Potential tricky issues:
  - What about charge created inside the diode ?
    - (increases locally effective epi thickness)
  - Is the Epitaxial layer thickness really known ?
    - Exact doping profile not known in principle
  - Is GEANT4 able to compute energy deposition in very thin material (10-20  $\mu\text{m}$ ) ?

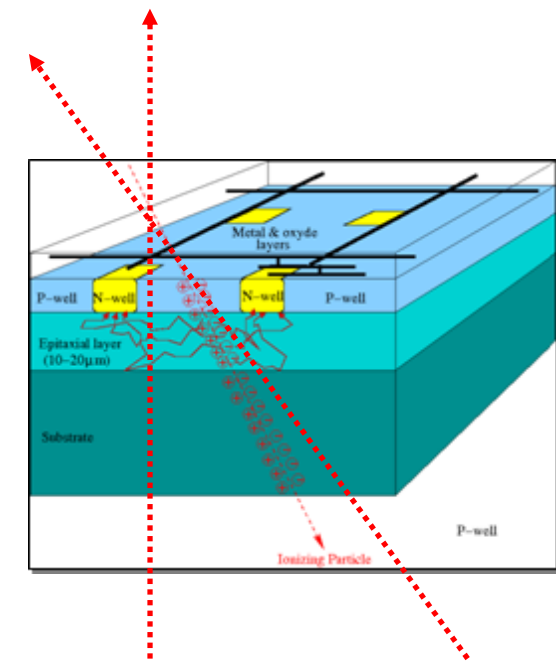
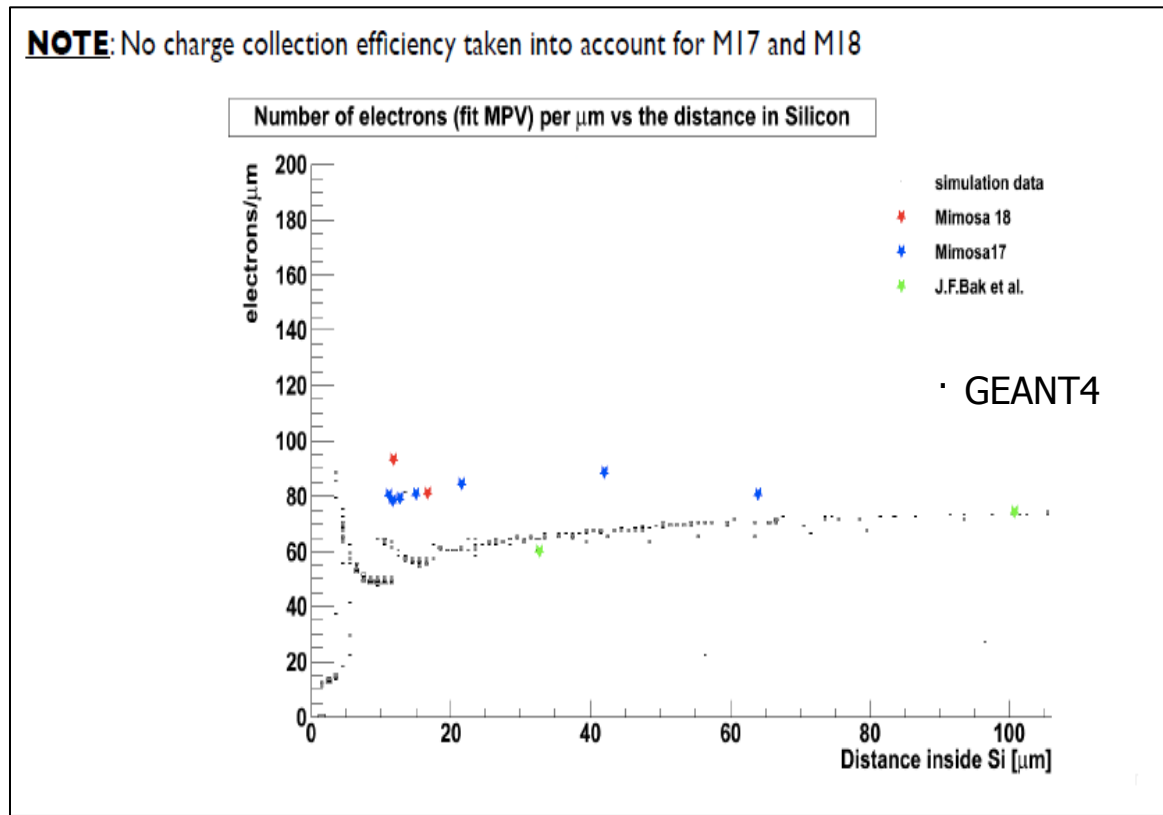
## Energy deposition in thin silicon devices (A.Geromitsos)

Number of  $e^-$   
created per  $\mu\text{m}$   
(MPV value)



## Step 2: Energy deposition in thin silicon devices (A.Geromitsos)

- (large values obtained with large incident angle)
  - GEANT4 underestimate charge creation for thin devices
    - Charge creation taken from test beam data



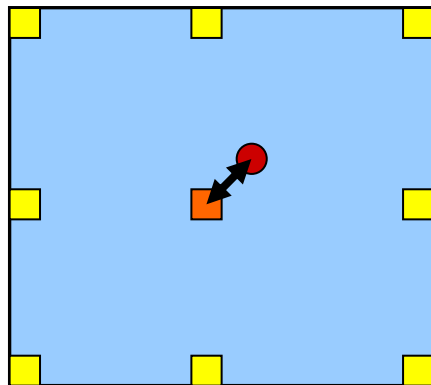
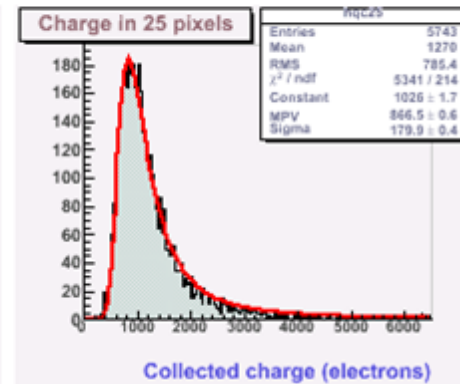
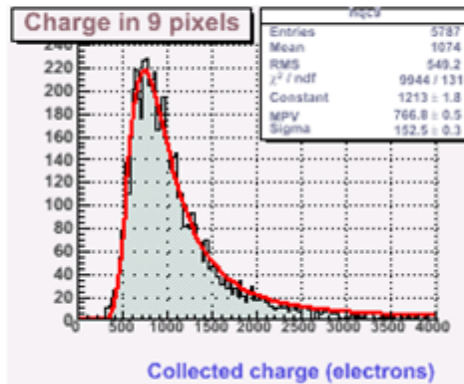
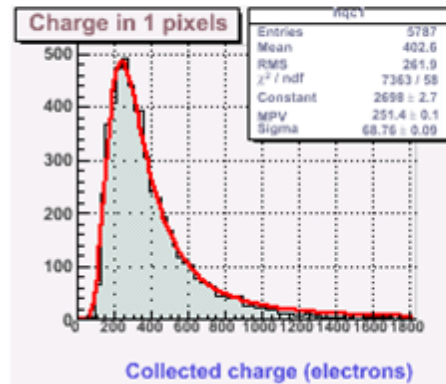
Large incident angle  
= increased effective  
thickness  
of the epi. layer

⇒ Chose a Landau with a MPV=80 e-/ $\mu\text{m}$

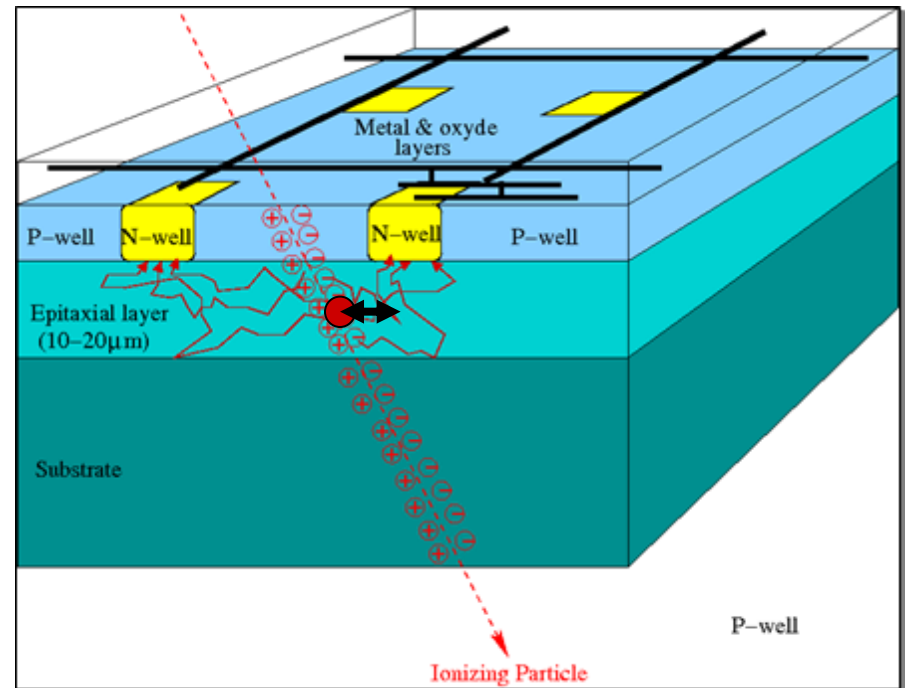


# Seed impact distance and charge collection

M9 ; run 9552; PI 9, sub 1, dist 60; Gain 5.90; eff 100.000 +- 0.017; Seed 5.0; Neigh 2.0

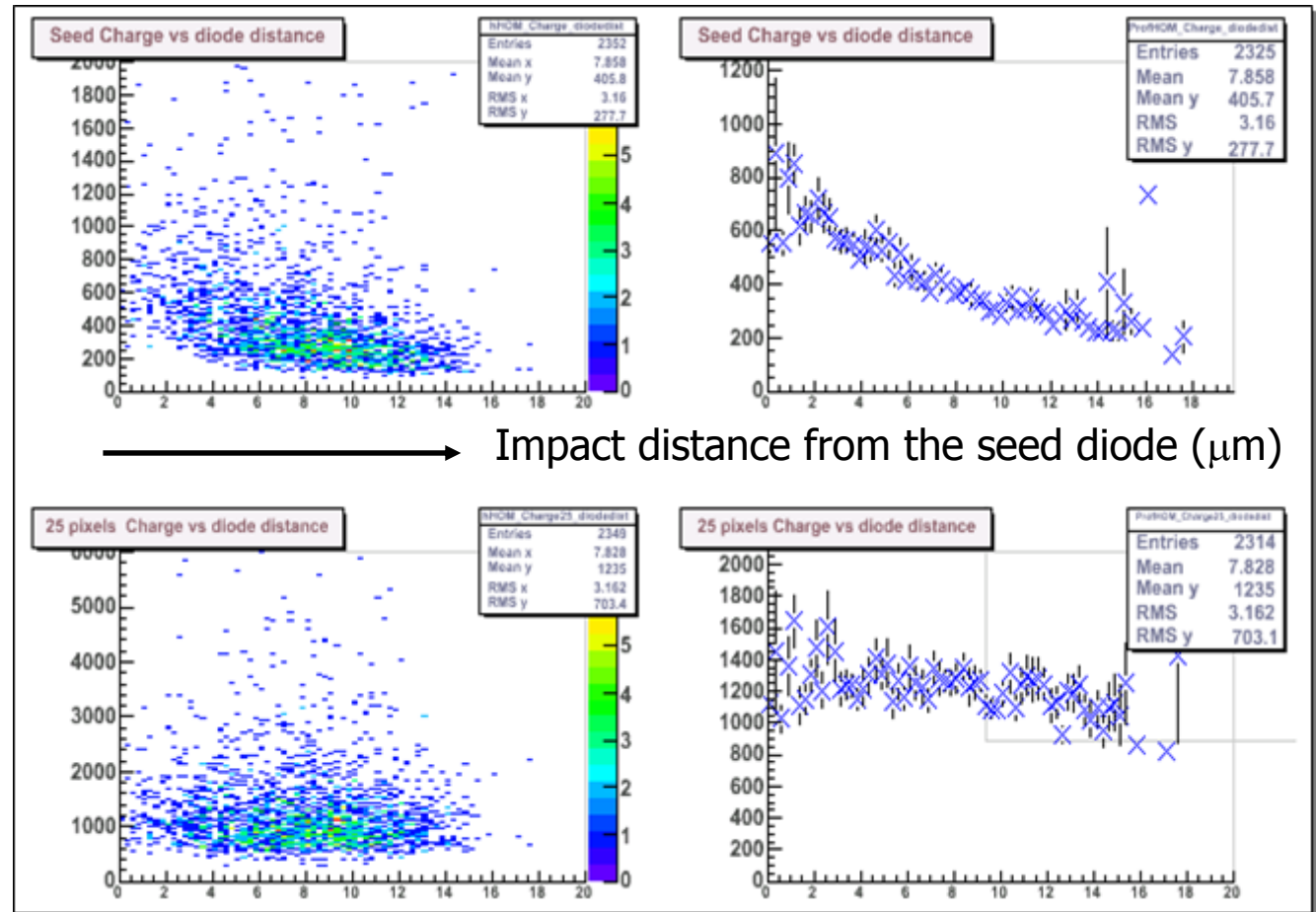


- = Collecting diodes
- = seed diode
- = Impact position
- = seed-impact distance



# Charge vs seed-impact distance

Collected charge (e-)  
In seed pixel



Collected charge (e-)  
in the whole  
cluster (5x5)

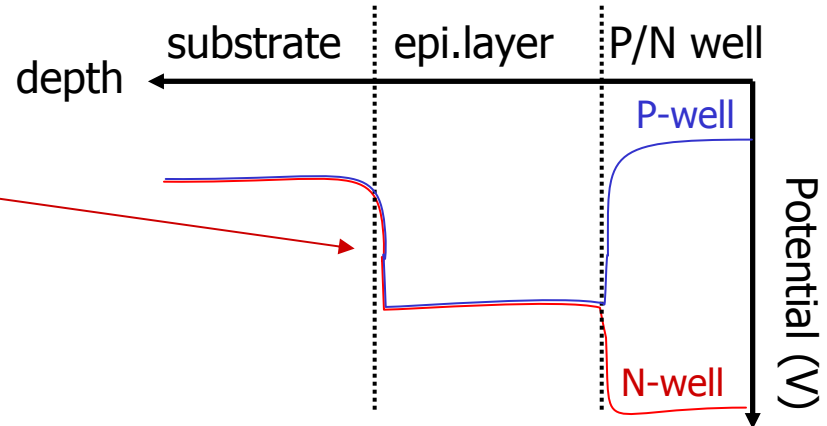
- Charge in seed depends highly on impact position but total charge is « almost » constant
  - Global Charge collection efficiency is constant as a first good approximation
  - We can separate charge creation and charge collection in 2 independent steps.
  - Charge creation can be parametrized with on only one parameter = **Effective epitaxial thickness** for a given prototype

# Step 3: Charge transport and charge collection

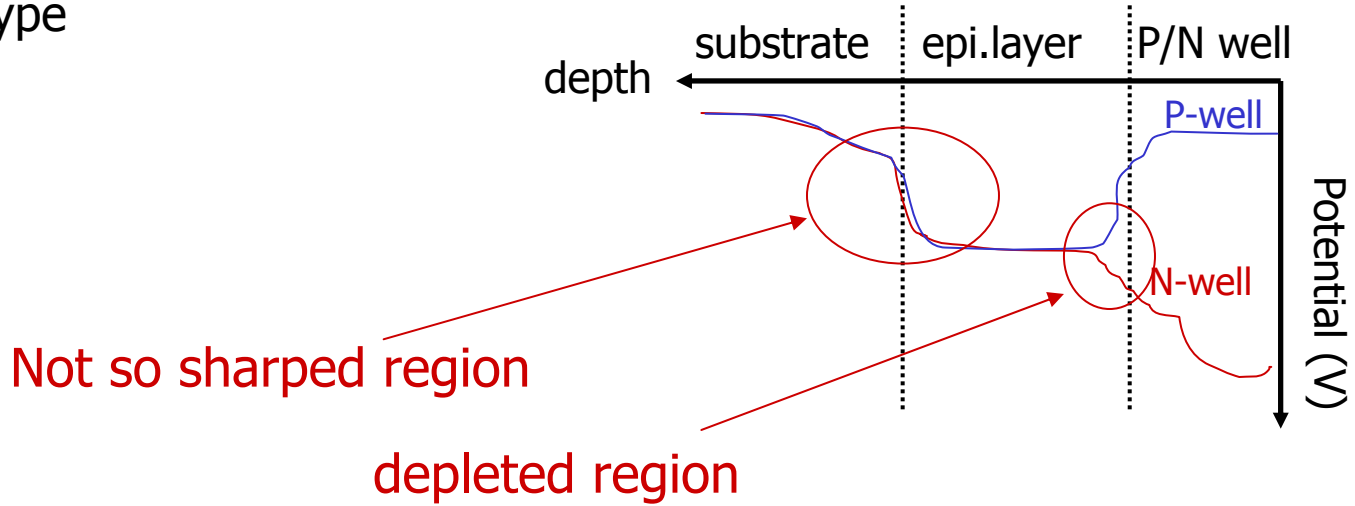
- Goal
    - Build a data driven model with a reasonable number of parameters
  - Physical parameters:
    - Collecting charge diode (N-Well)
      - pitch
      - Surface
      - Depleted region
    - Doping profile
      - Epitaxial layer thickness
      - Epitaxial layer – Substrate interface
        - Perfect reflexion of charge ?
      - Charge Collection Efficiency
        - Is it constant ?
- Not always known perfectly  
(e.g. doping profile)
- From our data
    - Total collected charge ( $e^-$ )
    - Charge distribution between pixels
    - Noise ( $e^-$ )
    - Charge collection efficiency ( $> \sim 90-95\%$ )
      - Effective epitaxial thickness
    - ADC gain and dynamic range
- Measurable from  
lab and beam test  
(easier with analog output !)

# Step 3: Potential profile

- Schematical profile
  - Ideal case

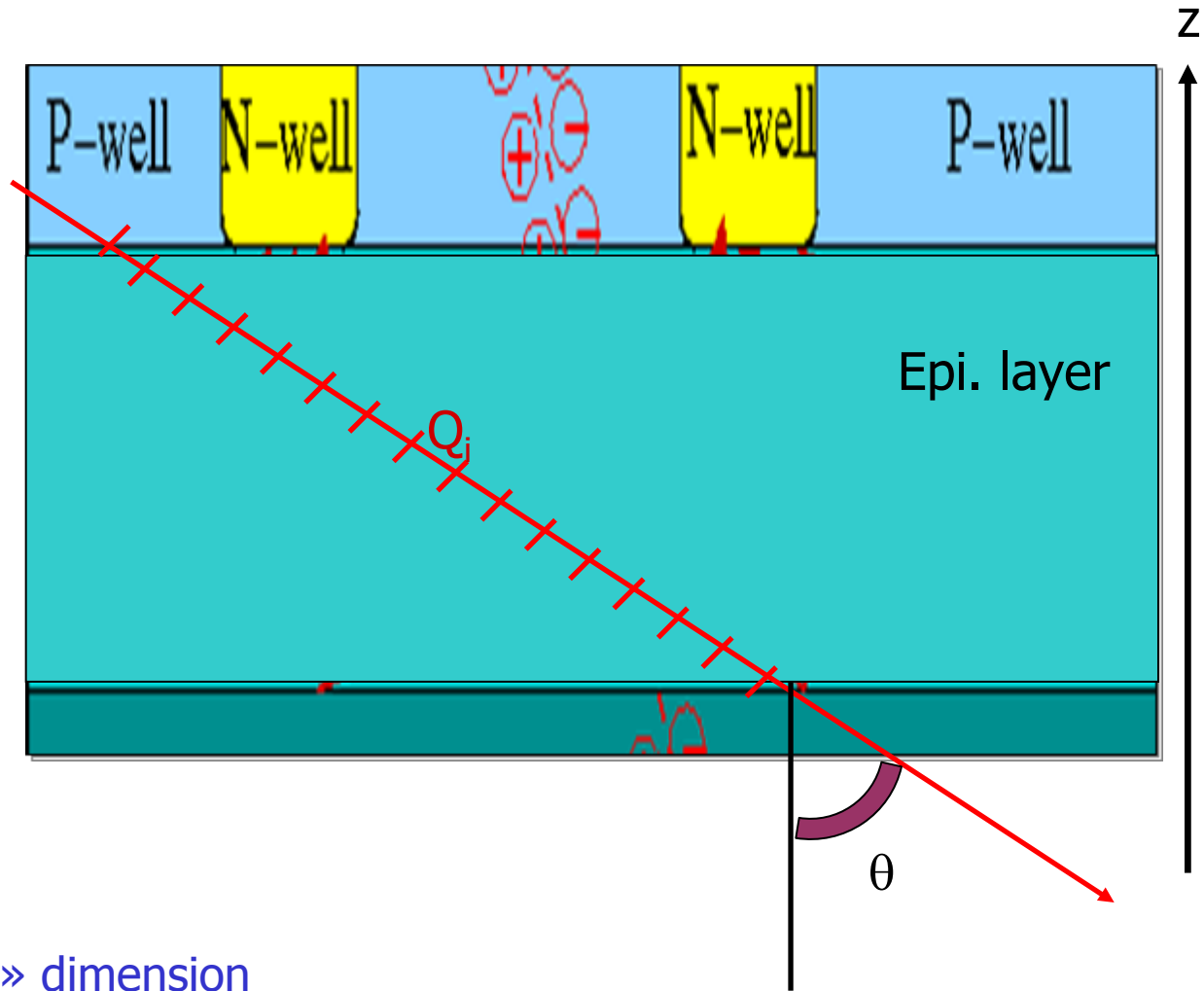
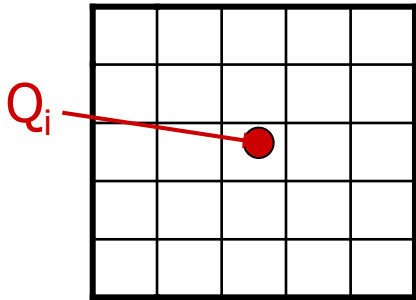


- Measure an effective epitaxial layer  
For each prototype



# Step 3: segmentisation

- Divide the track
  - N segments  $i$
  - $Q_i = Q_{tot} / N$
- $Q_i$  can be as low as  $1 e^-$ 
  - More CPU
  - More detailed
  - Option assumed in the following slides
- compute 25 probabilities of Charge  $Q_i$  to reach pixel  $j(1,25)$



- Model independant of «  $z$  » dimension
  - But able to deal with tracks having  $\theta \neq 0$

# Step 3: What we know/observe from our data

---

- Results taken from Mimosa 9/18 chips
  - (AMS-opto 0.35, not HR)
  - Analog output (actually 12bits ADC)
  - 10,20,30,40 um pitch
- Informations provided by beam test/lab test
  - Gain (e-/ADC)
  - Charge collection efficiency
  - Effective epitaxial layer thickness
    - Obtained from cluster total charge
  - Performances
    - S/N, efficiency, fake rate, resolution, multiplicity, etc.

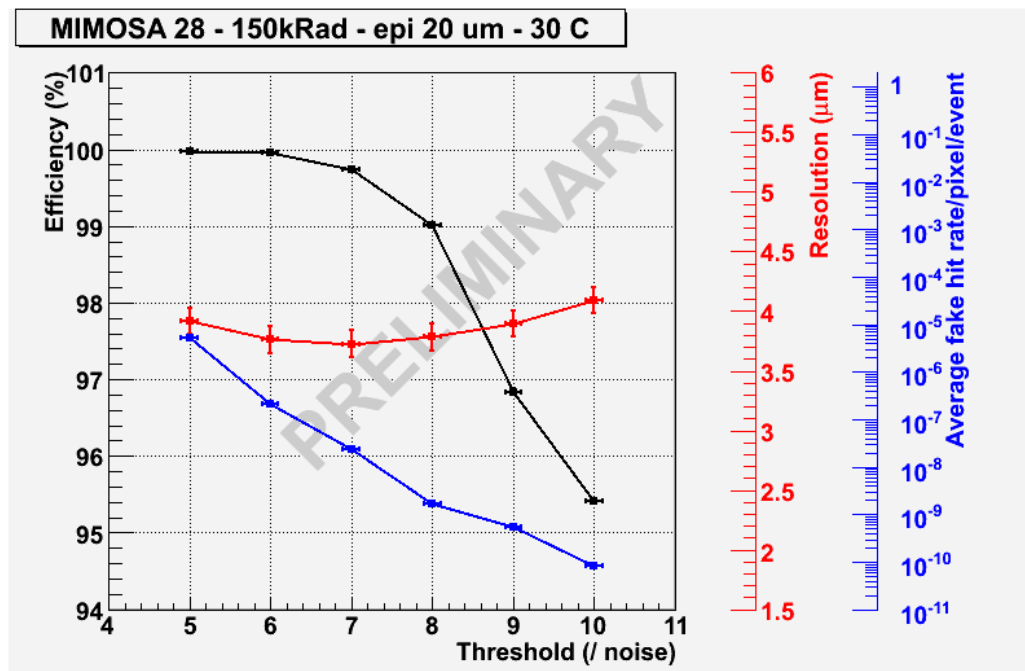
# What about chips with digital output ?

---

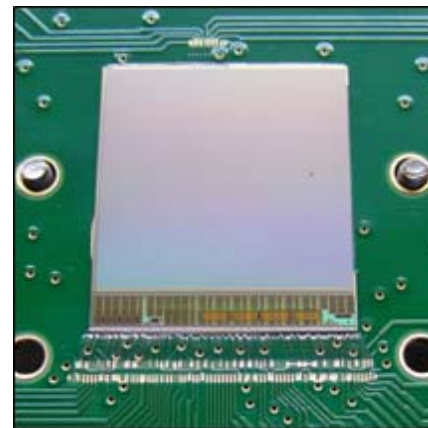
- Ultimate sensor for STAR HFT:
  - No charge recorded but threshold scans are available.
  - Test beam already performed
- Benchmarks
  - Efficiency/fake rate vs discriminator threshold
  - Multiplicity distribution vs discriminator threshold
  - Resolution
- Goal:
  - realistic occupancy, resolution, fake rate, efficiency, double hit separation.
  - Avoid if possible a deterministic response of the digitizer.

# STAR – Ultimate : Performances

- Test Beam @ CERN-SPS (July 2011), 120 GeV pion beam
  - Goal: approach STAR running conditions
    - $T = 30\text{ }^{\circ}\text{C}$
    - Chip irradiated @ 150 kRad
    - Read-out time = 198  $\mu\text{s}$
- Results
  - Efficiency  $\geq \sim 99.9\%$  with a  $\sim < 10^{-6}$  fake rate
  - Spatial resolution  $\sim 3.7\text{ }\mu\text{m}$
  - Uniformity checked
- Under study / to be done
  - Fluence of  $> 3 \times 10^{12}\text{ } n_{\text{eq}}/\text{cm}^2$  (already tested with previous prototype M26)
  - Large incident angle



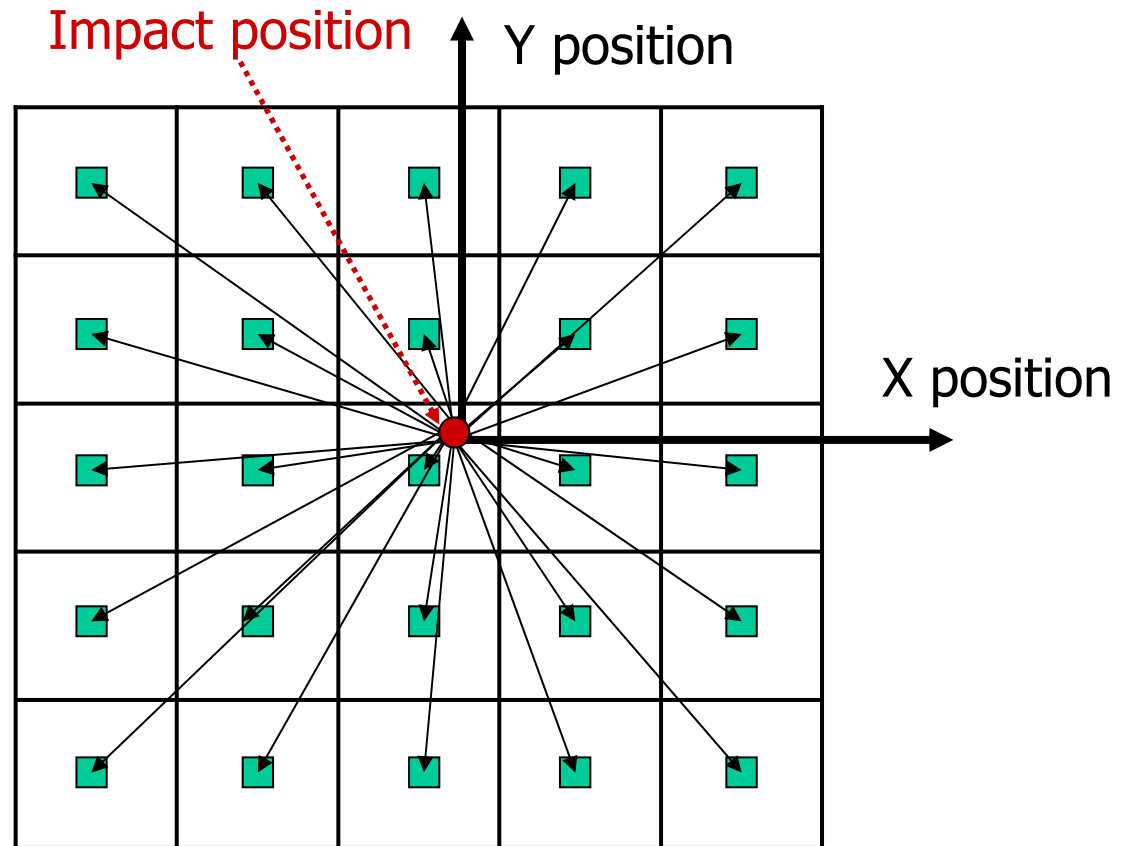
Ultimate sensor fulfilling STAR requirements demonstrated





# Collected charge vs impact position (analog output case)

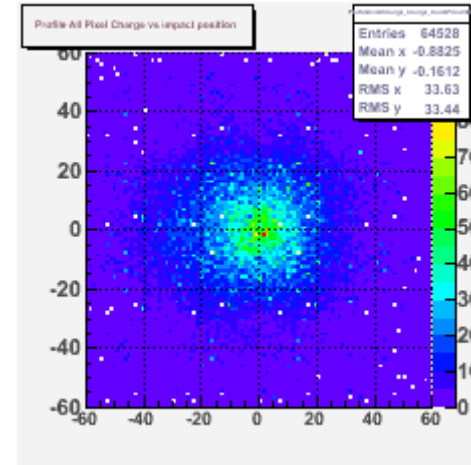
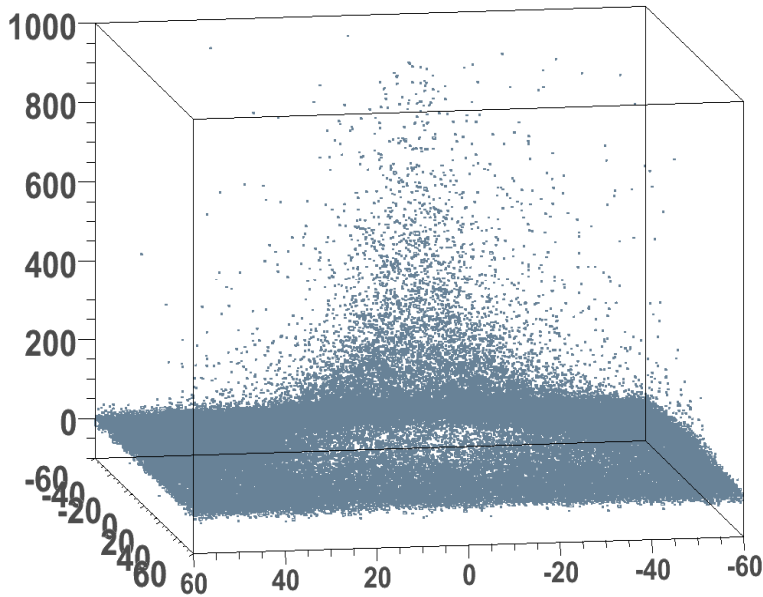
- For each event
  - Impact position from the telescope defines the origin
  - Store 25 x 3D vectors
    - $\{x(\mu\text{m}), y(\mu\text{m}), Q(e^-)\}$
- Plot all this vectors in a Single 3D plot
- All the useful information should be contained in this plot
  - Use it as a probability density function



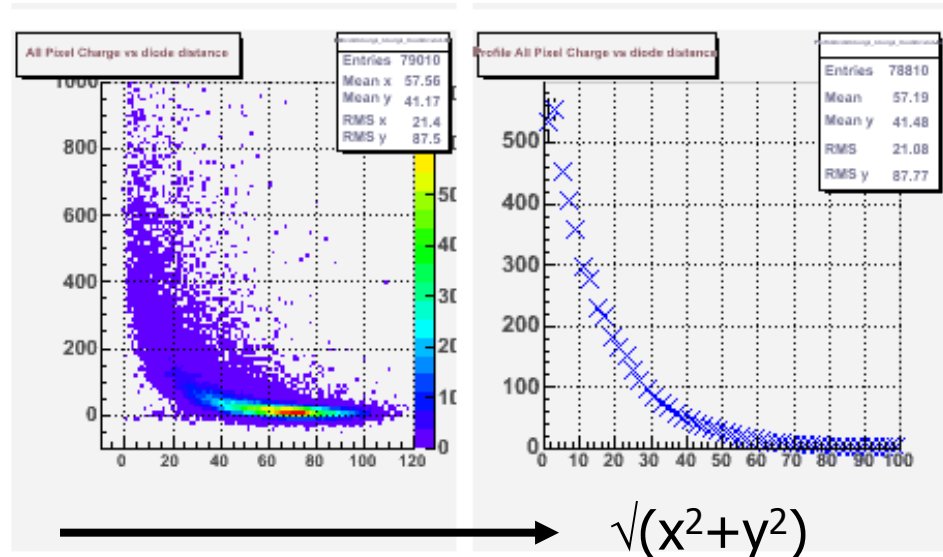
# Collected charge vs impact position (2)

- Example (30 um pitch)

All Pixel Charge vs impact position



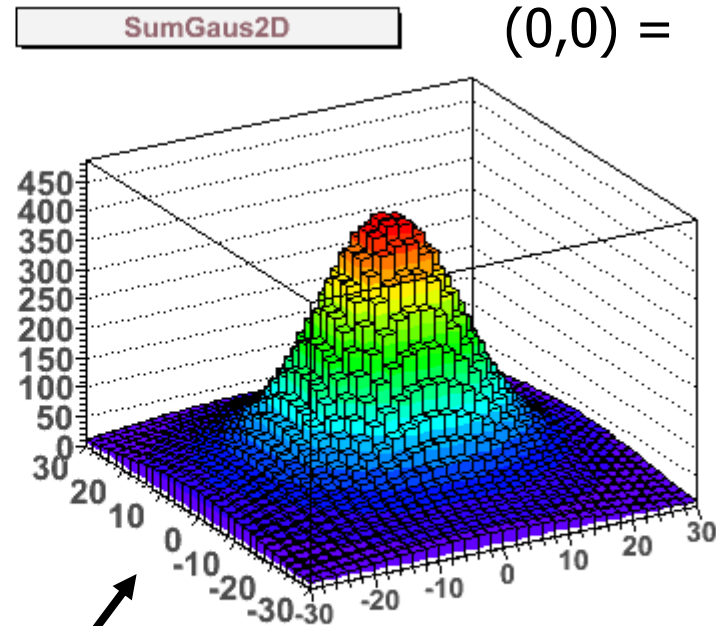
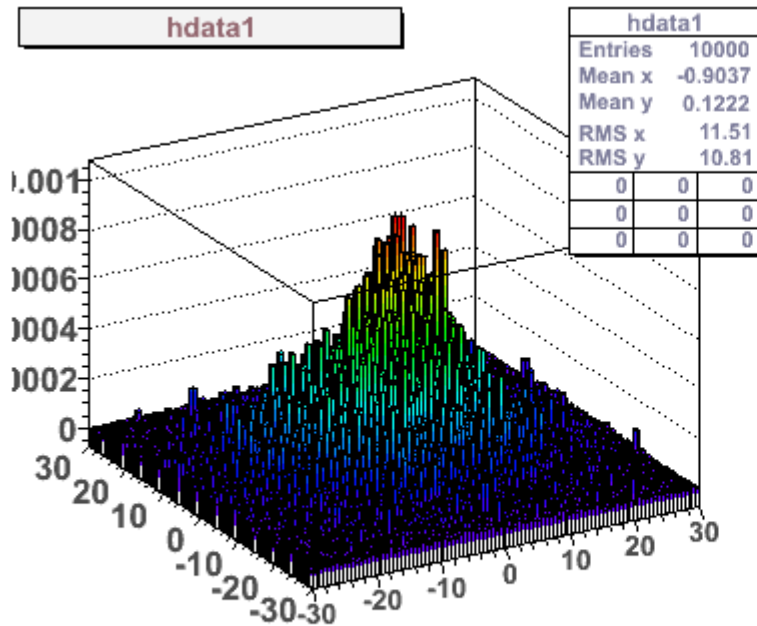
Q  
↑



# Collected charge vs impact position (4)

- Take the profile of the previous plots and fit it with
  - $F(x,y) = \text{sum of } 2 \times 2\text{Dgaussian}$

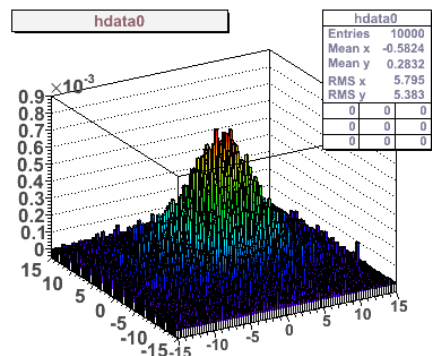
$$e^{-\frac{x^2+y^2}{2\sigma_1^2}} + w \times e^{-\frac{x^2+y^2}{2\sigma_2^2}}$$



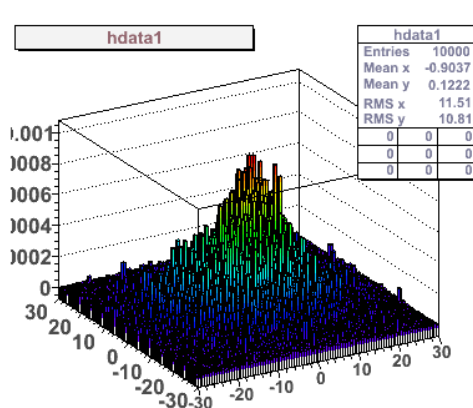
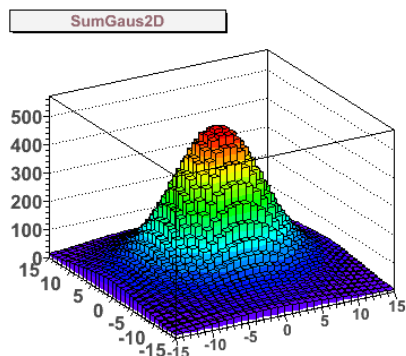
Defines a probability density function for charge  $Q_i$  to reach pixel  $j$  which is at  $(x,y)$  w.r.t. the impact

⇒ 25 probabilities

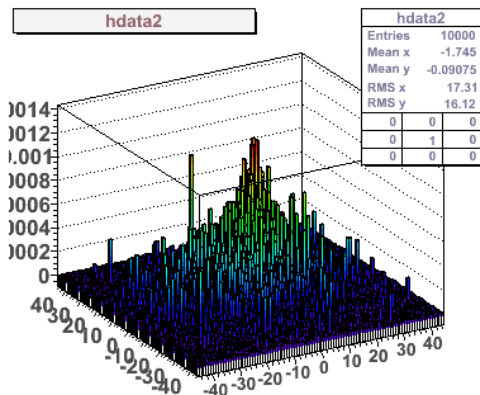
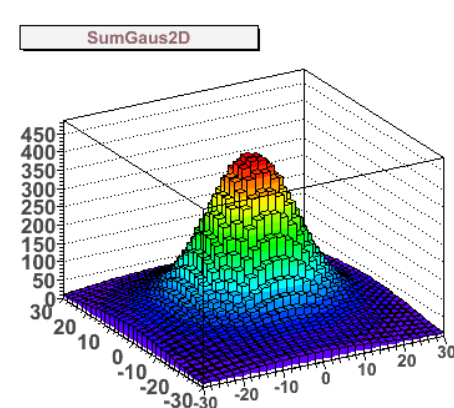
# Collected charge vs impact position (3)



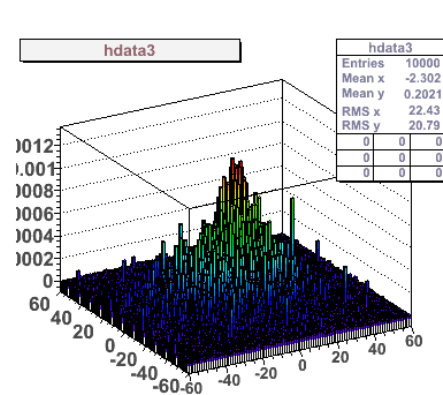
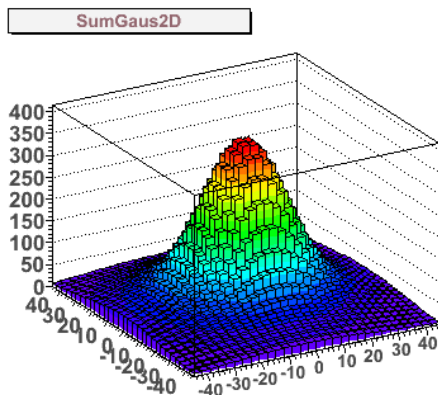
10  $\mu\text{m}$  pitch



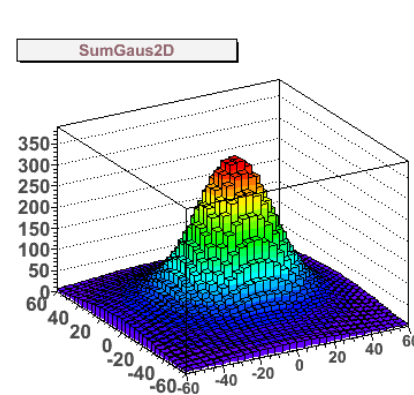
20  $\mu\text{m}$  pitch



30  $\mu\text{m}$  pitch



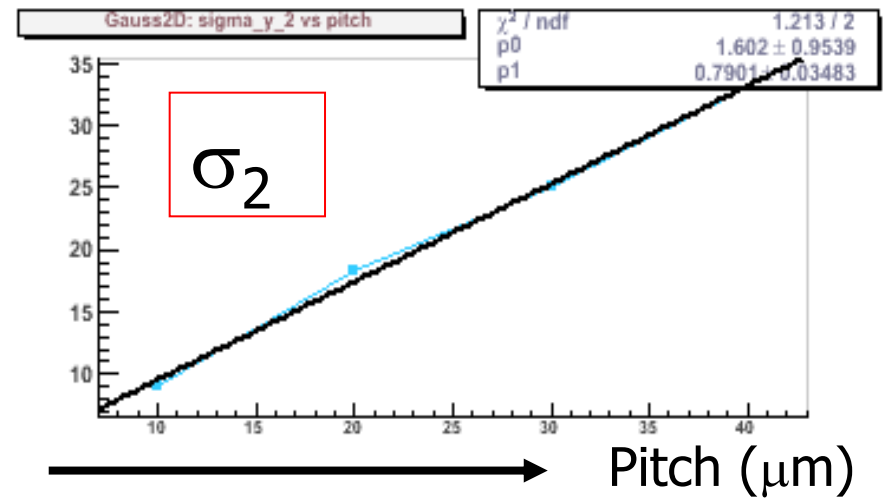
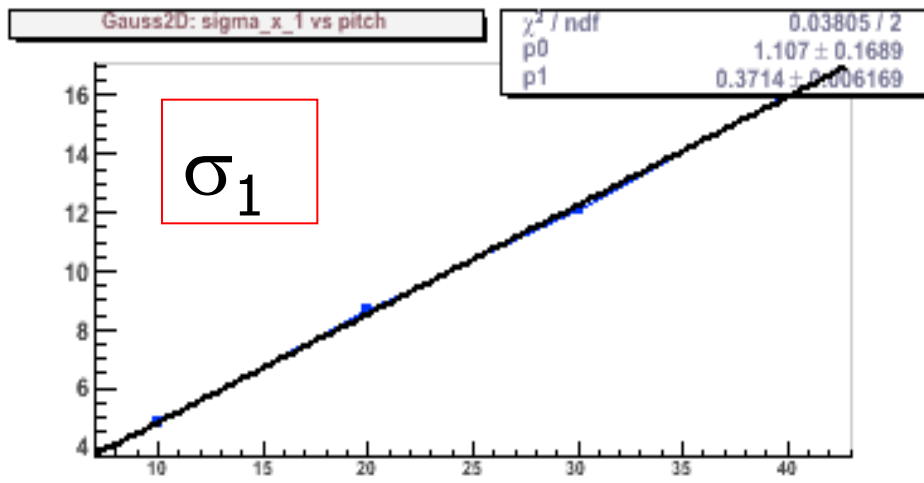
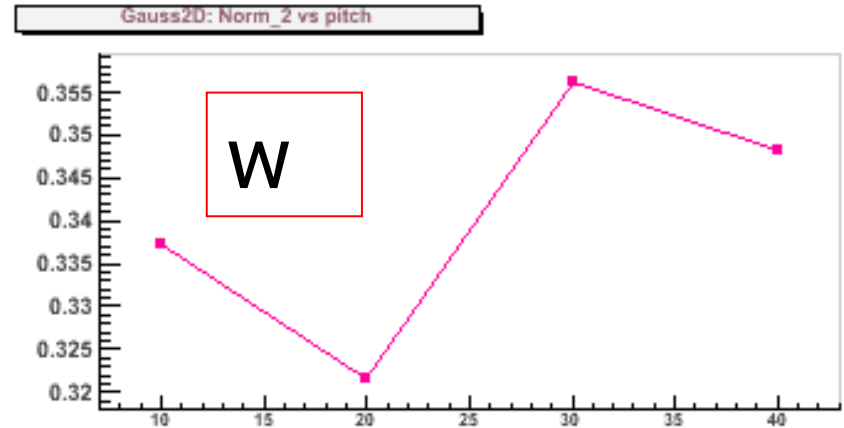
40  $\mu\text{m}$  pitch



# Collected charge vs impact position (5)

- Linearity vs pitch  $\Rightarrow$  5 parameters for all pitches

$$e^{-\frac{x^2+y^2}{2\sigma_1^2}} + w \times e^{-\frac{x^2+y^2}{2\sigma_2^2}}$$



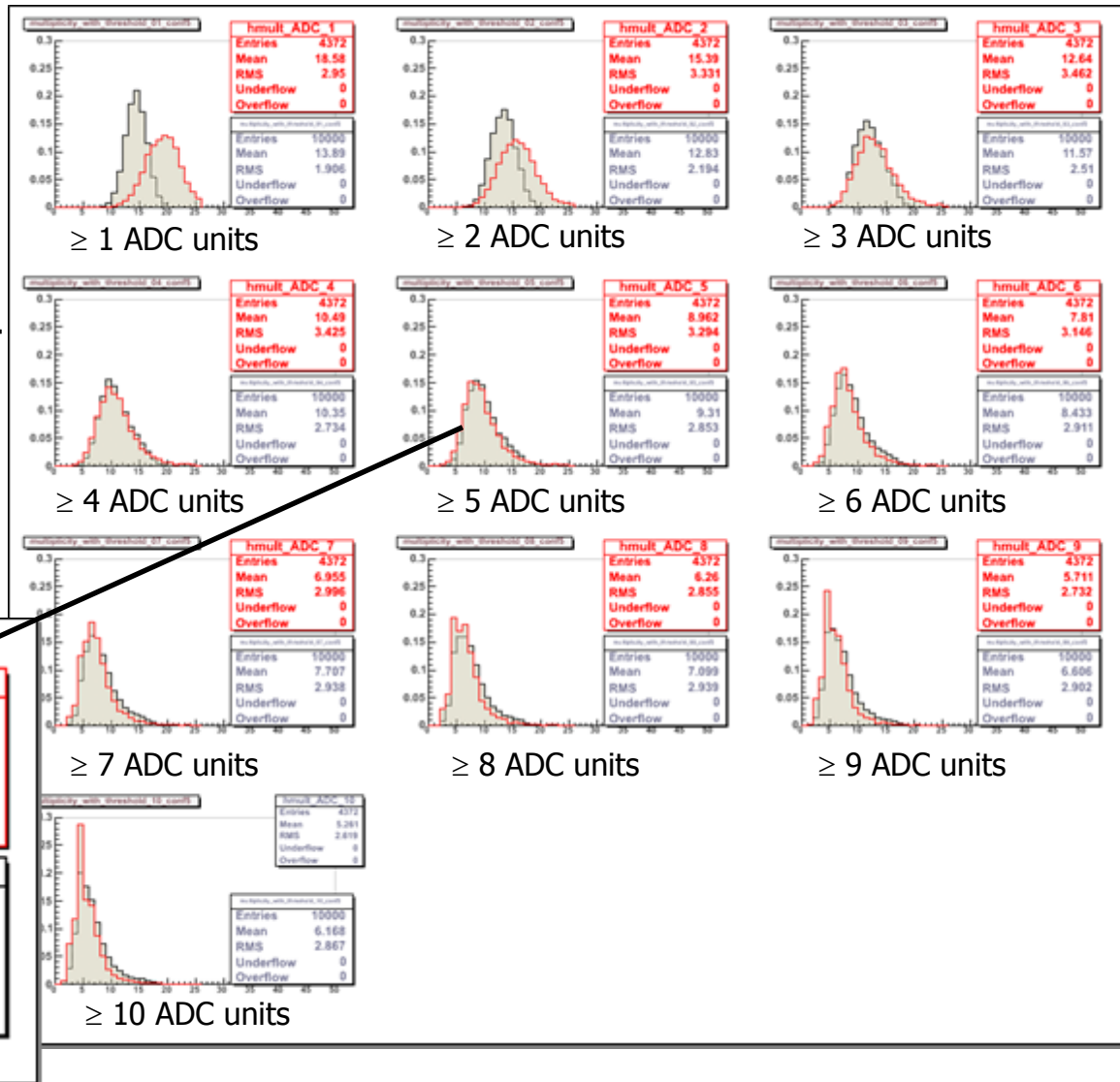
Are results close to real data ?

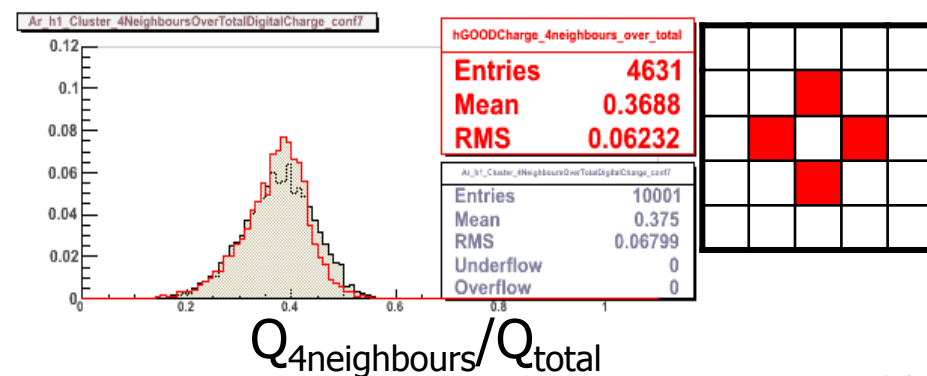
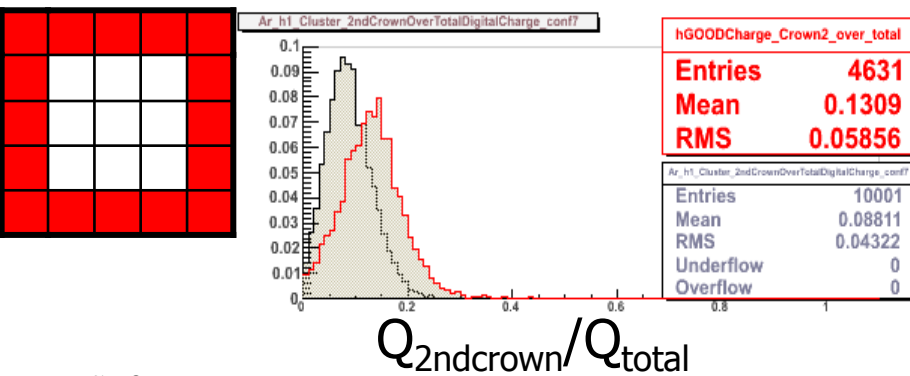
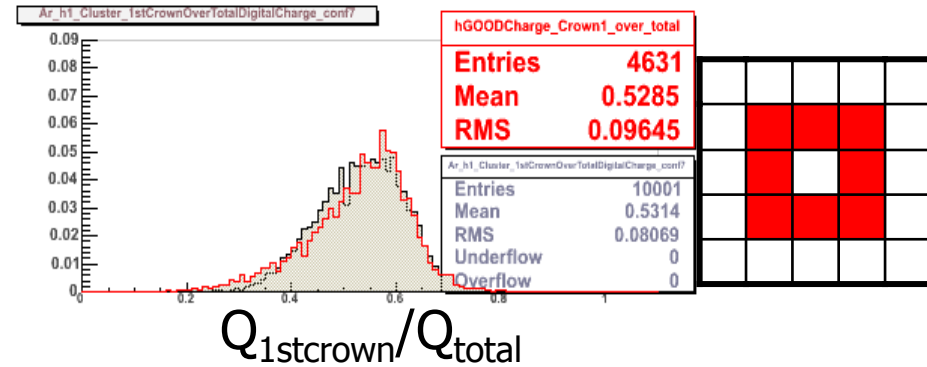
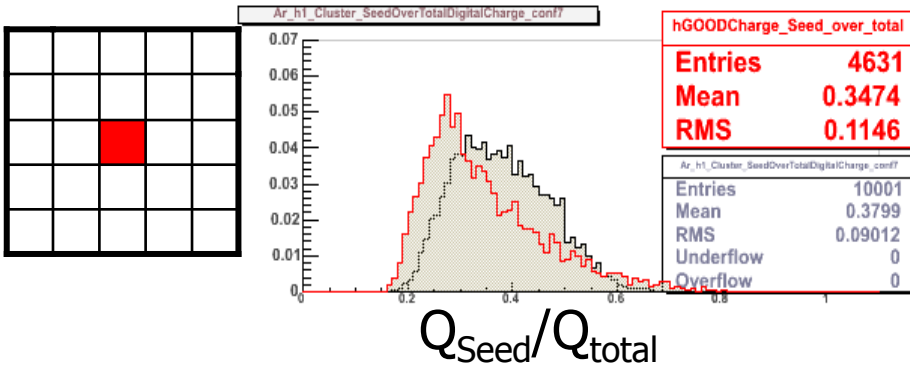
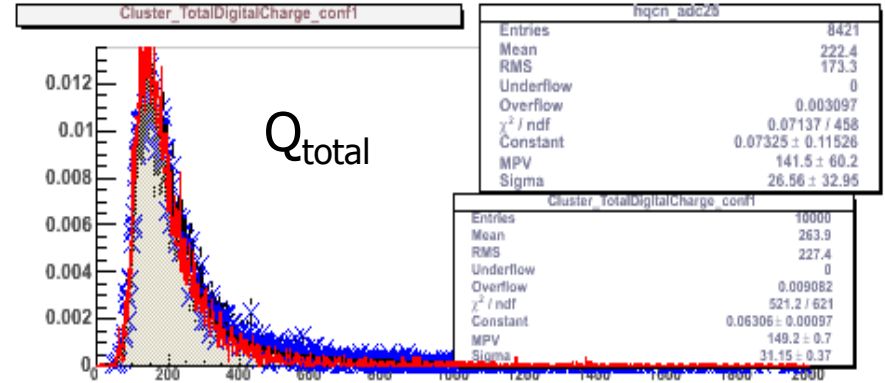
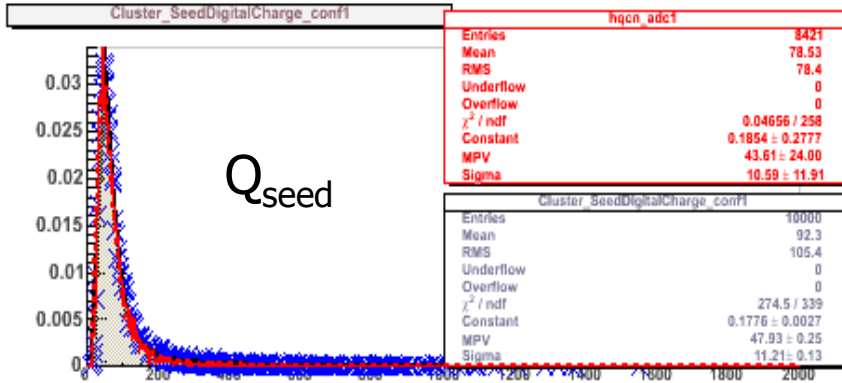
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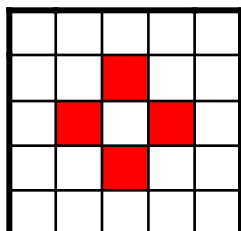
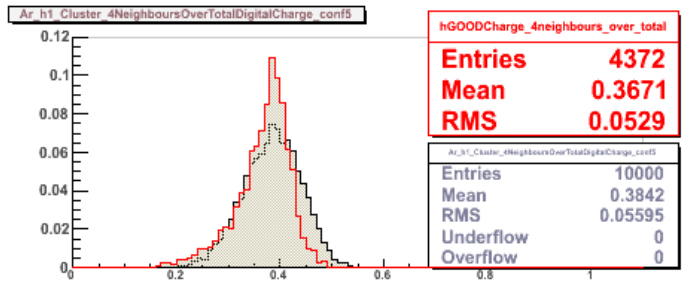
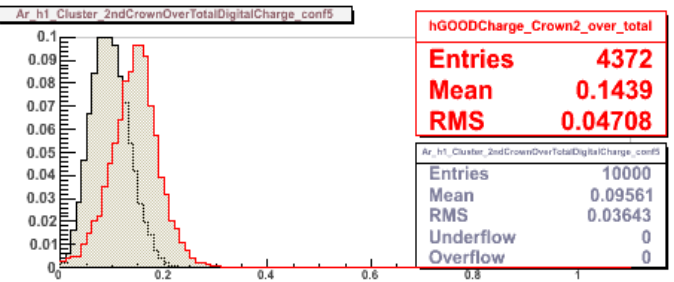
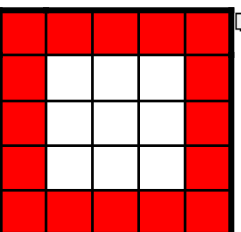
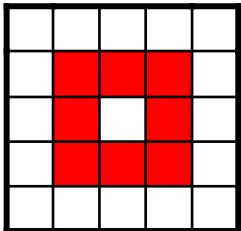
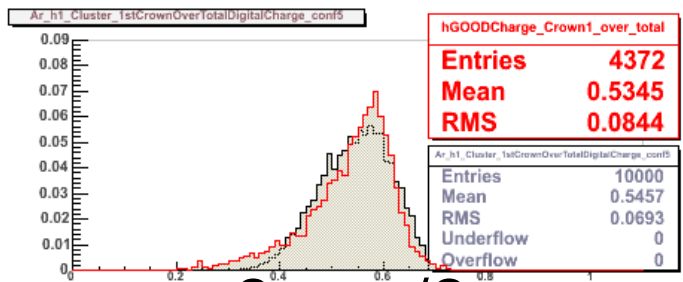
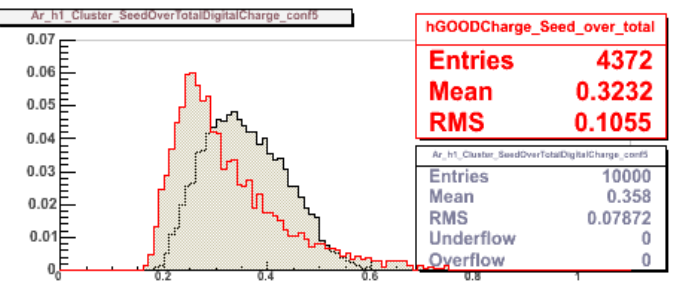
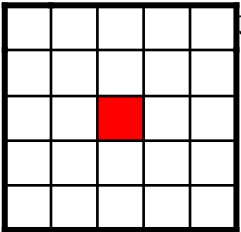
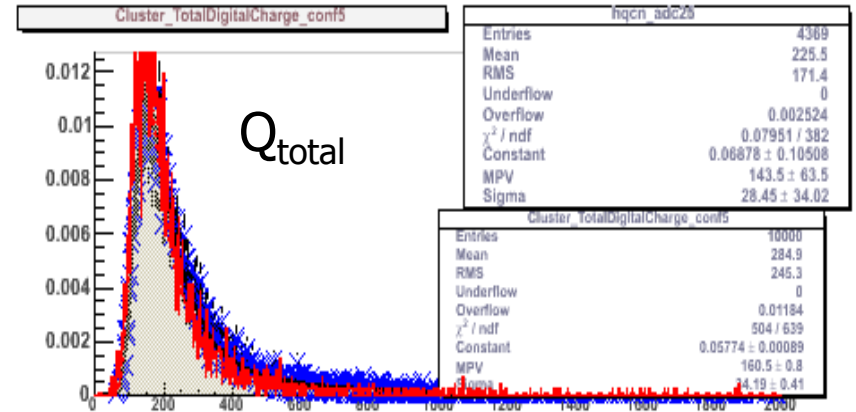
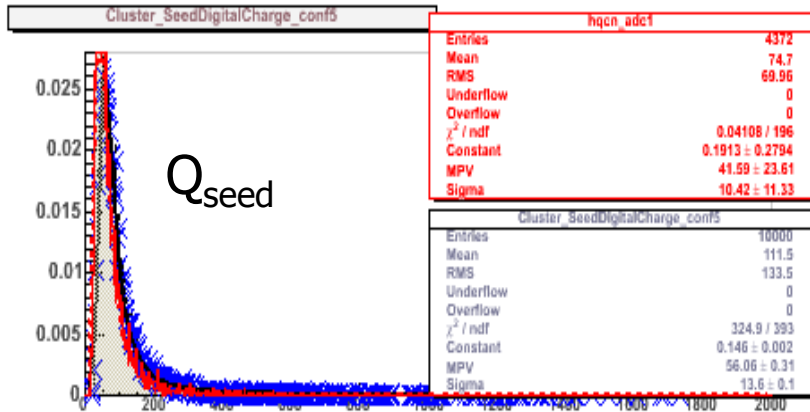
# DIGMAPS: Some preliminary results (20 um pitch)

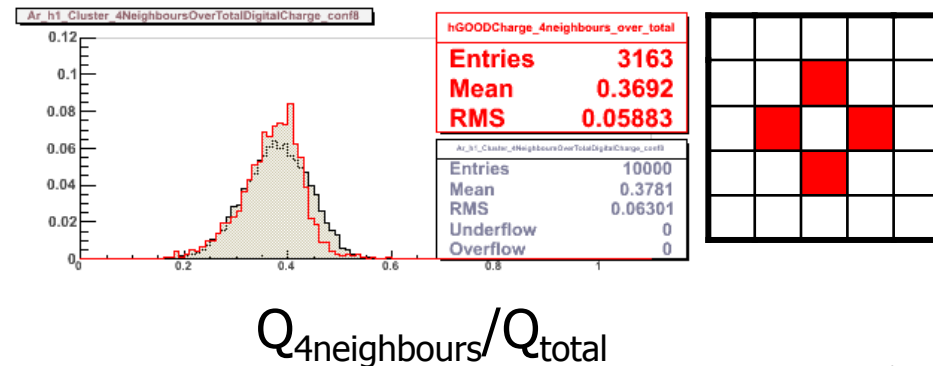
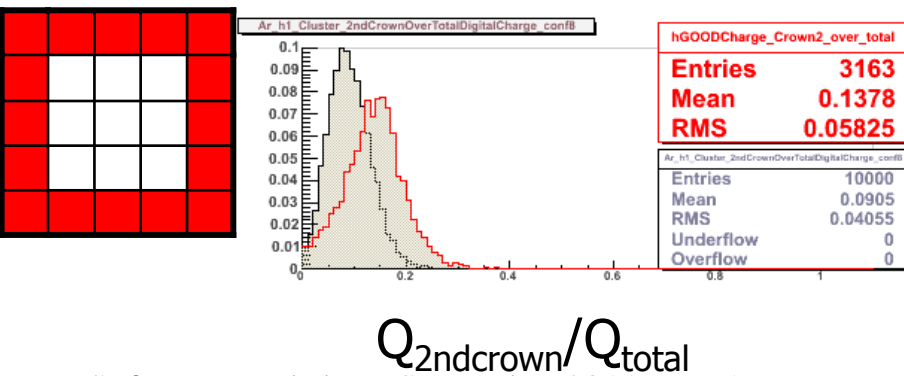
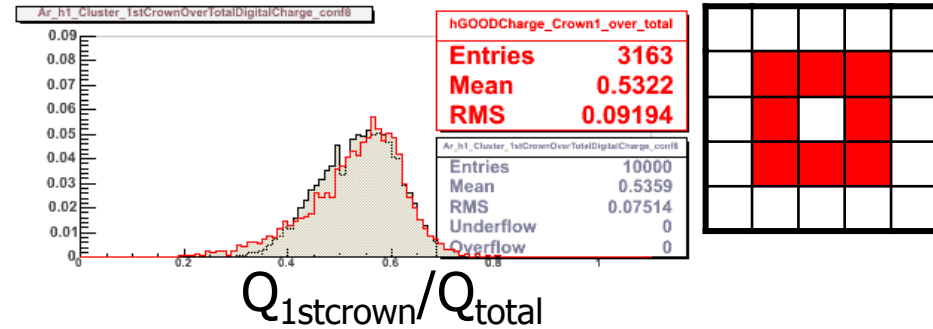
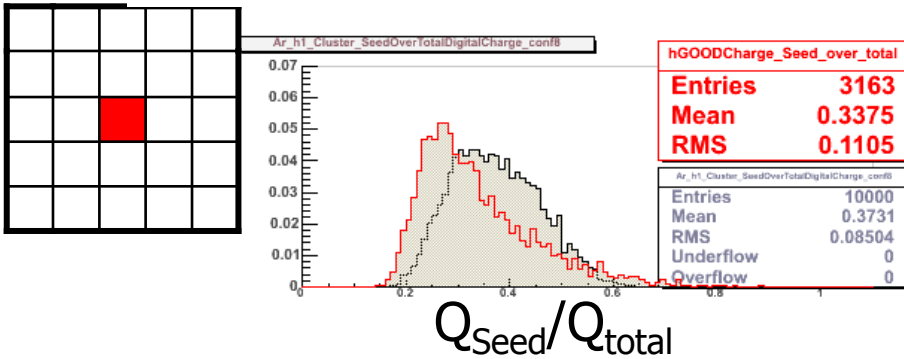
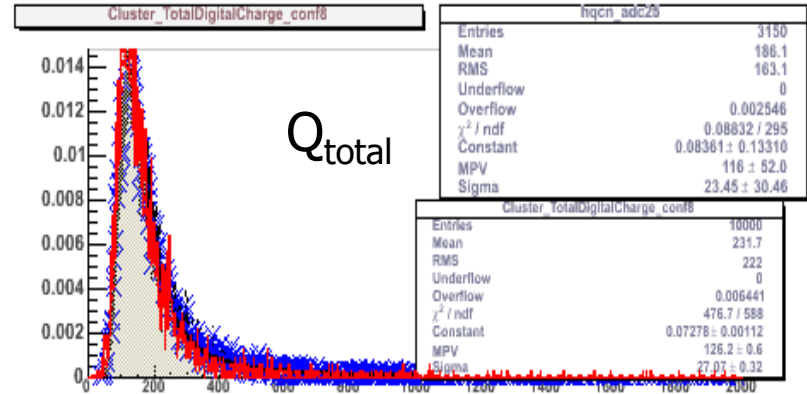
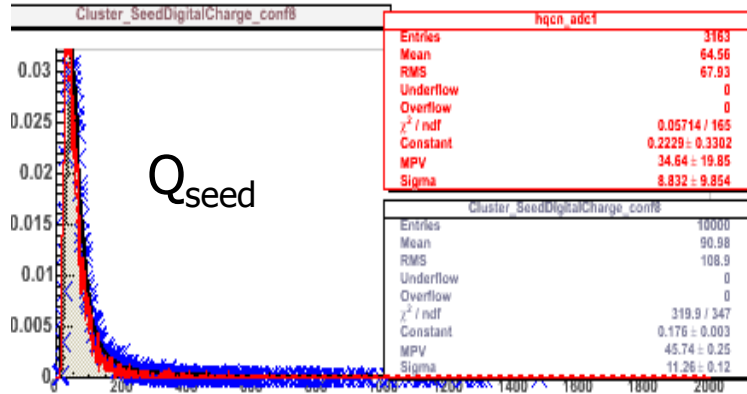
- Nothing optimized !
    - DIGMAPS model
    - DATA
  - Multiplicity distribution
    - Number of pixels in cluster
    - For different ADC cuts
- 1 ADC unit  $\sim 5.9 e^-$   
(Noise =  $9.2 e^-$ )

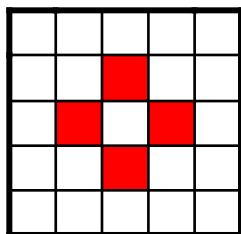
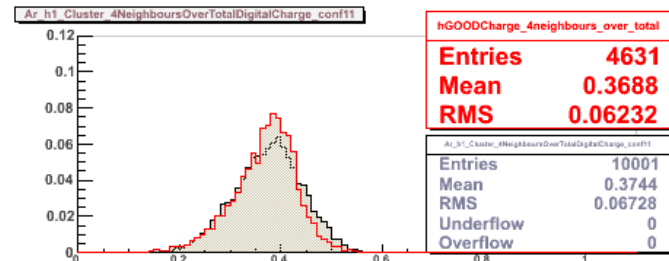
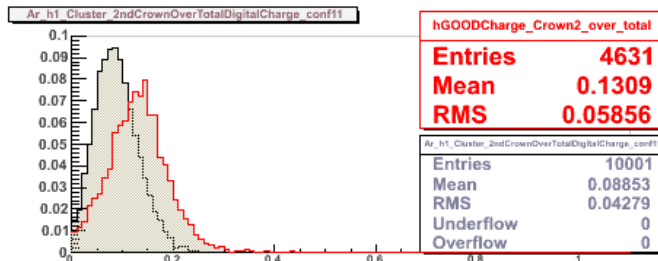
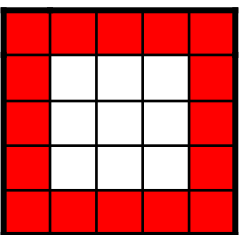
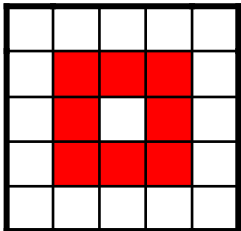
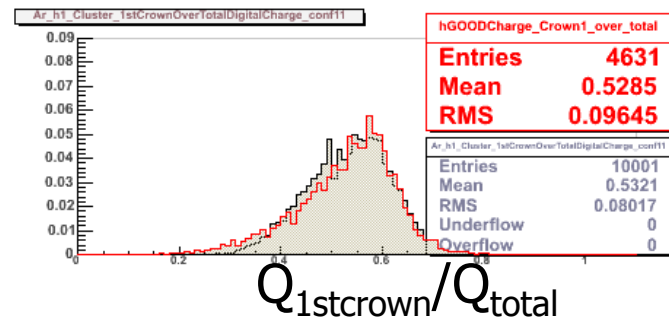
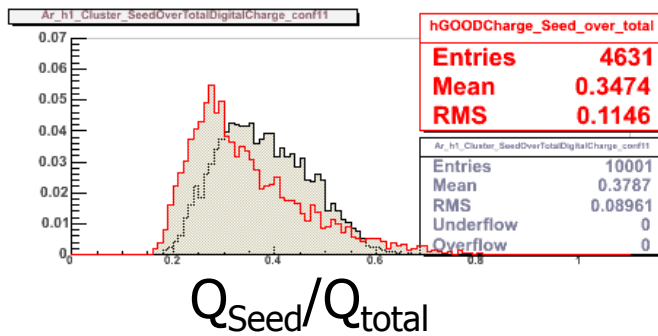
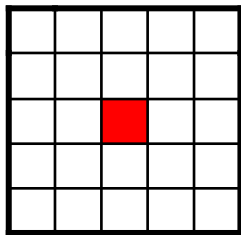
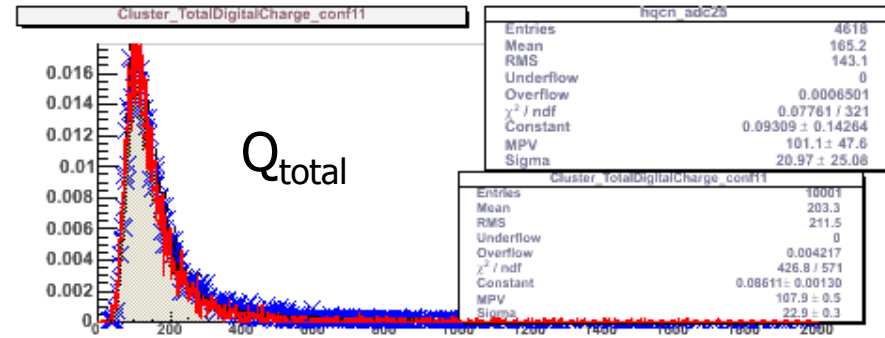
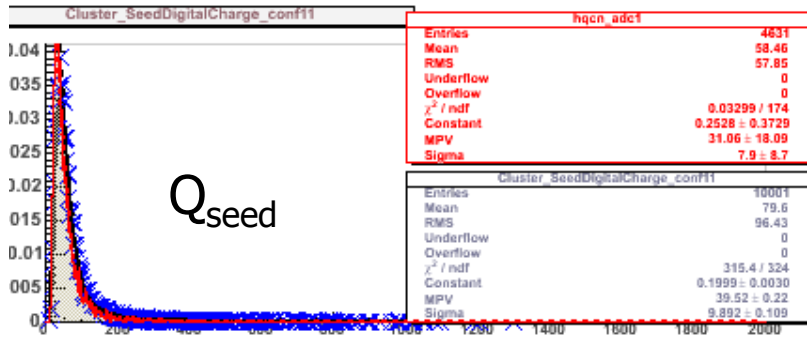






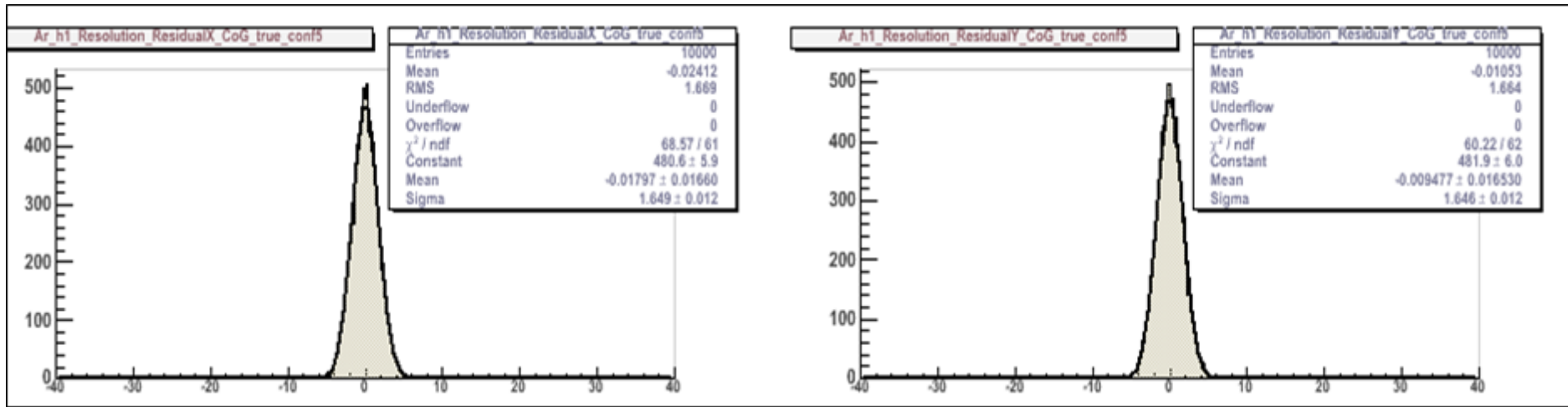






# Resolution ( $\mu\text{m}$ )

- E.g. M9, 20  $\mu\text{m}$  pitch



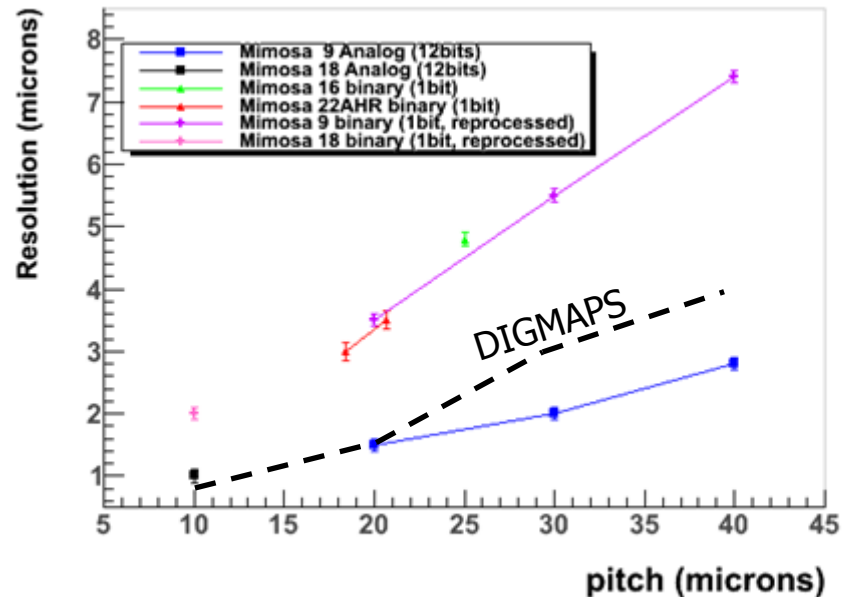
DIGMAPS model

$$\sigma_{(\text{CenterofGravity})} \sim 1.7 \mu\text{m}$$

DATA

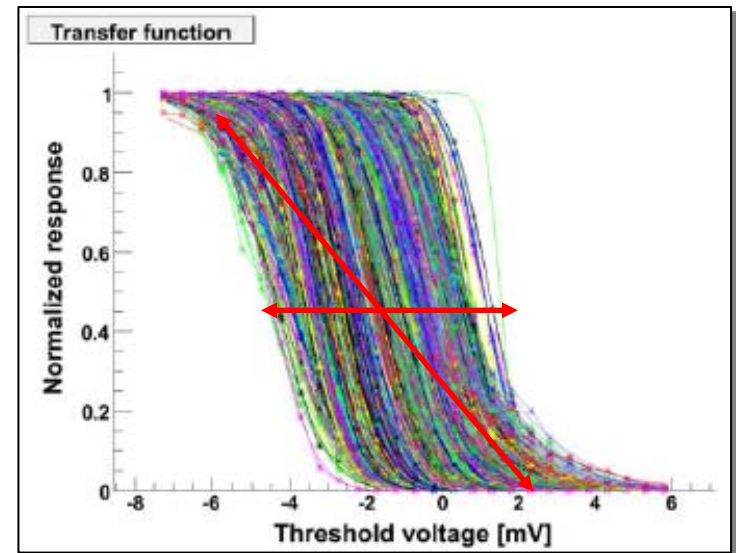
$$\sigma_{(\text{CenterofGravity})} \sim 1.8 \mu\text{m}$$

Not so good agreement for larger pitch...



# Step 4/5 (ADC and cluster algorithms)

- Under development
  - Only perfect clustering at the moment
  - Only perfect ADC/discr.
    - Realistic Noise treatment to be added  
FPN + Temporal Noise
    - Zero suppression to be added



FPN / Temporal Noise

# Performances: summary

---

- Fit / model not optimized
  - Address more carefully the weight of 2<sup>nd</sup> crown pixels
    - small number of entries  $\Rightarrow$  uncertainty underestimated
    - Reduce range of the 2D fit ?
  - Focus should be made on the response of the 8 neighbouring pixels
    - Determines multiplicity (particularly for digitized chips)
    - Determines resolution
    - Determines hit separation performances
  - Global response is already encouraging
    - Limited number of parameters (Noise, epitaxial layer + 2D double gaussian)
    - Multiplicity can be reproduced
    - Still many optimization to be done
  - Model could be simplified
    - each  $Q_i$  of a given segment has to be randomly addressed to one pixel
    - Option: suppress random part and charge only with PDF values.

# Outlook: implementing a digitizer in HFT-software

---

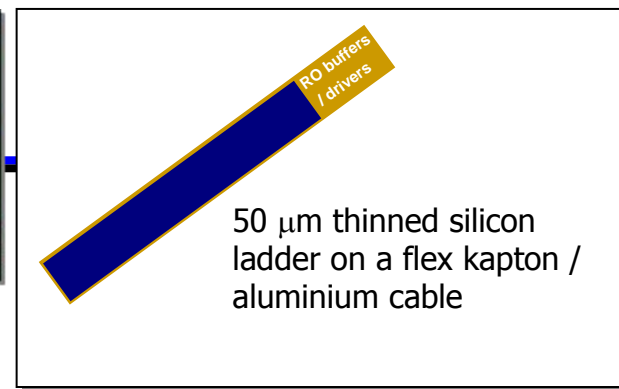
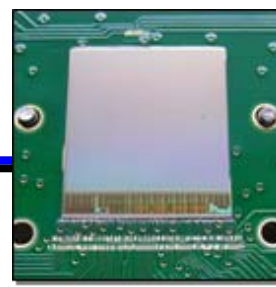
- DIGMAPS = Tool under development but allows already many studies:
  - sensor(s)/models with a digitised output
  - any other charge transport model
    - Optimize parametrized models for fast sim
  - Optimize ADCs/discris
    - N bits, dynamic range, Noise, etc.
  - clustering algorithms
    - chip occupancy
    - Hit separation performances
  - Zero suppression blocks, etc.
  - Study incident angle effects
  - CPU performances vs models
- HFT simulation (Fast/full simulation)
  - Simulating charge transport can be CPU time consuming
    - You should define which amount of complexity/computing you can afford.
  - A lot of possible algorithms/approaches
    - DIGMAPS can help to decide which precision you want
    - Multiplicity vs incident angle/charge deposition/impact position = difficult to parametrize
  - Nevertheless, building a physical model is out of reach
    - Data driven approach
    - Use test beam data as input/guideline is the key

Back up





# Ultimate Sensor for STAR Vertex detector (1)



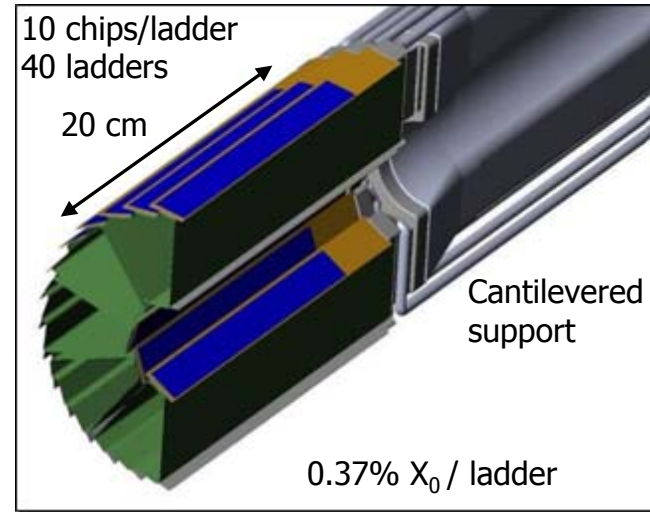
## STAR PIXL upgrade (physics run in 2014)

### Requirements

- $\sim 150$  kRad and few  $10^{12}$   $n_{eq}/cm^2/year$
- Temperature 30-35 °C (air flow cooling only)
- Power consumption  $\sim 130$  mW/cm<sup>2</sup>
- Spatial resolution  $< 10$   $\mu m$
- Integration time  $\sim < 200$   $\mu s$  to cope with occupancy ( $\sim 200$  hits / 4 cm<sup>2</sup> sensor / read-out cycle)

### Design

- 2 layers (2.5/8 cm radius)
- 40 ladders: 50  $\mu m$  silicon, Flex kapton / aluminium cable
- 10 Mimosa chips/ladder  $\Rightarrow 370 \times 10^6$  pixels
- 0.37%  $X_0$  per layer



## Ultimate (alias Mimosa 28)

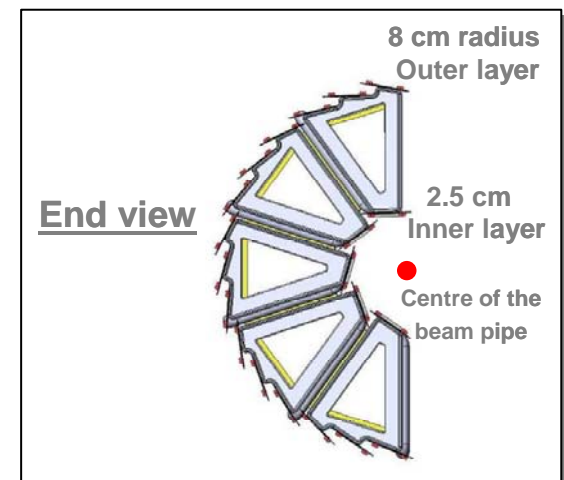
### Final sensor for the upgrade of STAR pixel layers of the vertex detector

- Design process Austria Micro System AMS-0.35  $\mu m$  - OPTO, 4 metal- and 2 poly- layers
- 15  $\mu m$  thick epi. layer, High-Resistivity substrate (400 Ohm.cm)
- Radiation tolerant structures
- 928 (rows) x 960 (columns) pixels, 20.7  $\mu m$  pitch  $\Rightarrow \sim 20 \times 23$  mm<sup>2</sup>
- Fast binary readout, zero suppression
- 200  $\mu s$  read-out time: Suited for  $10^6$  part/cm<sup>2</sup>/s

Chip delivered in spring 2011

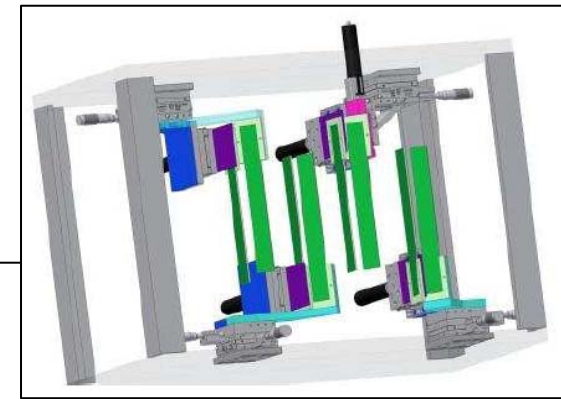
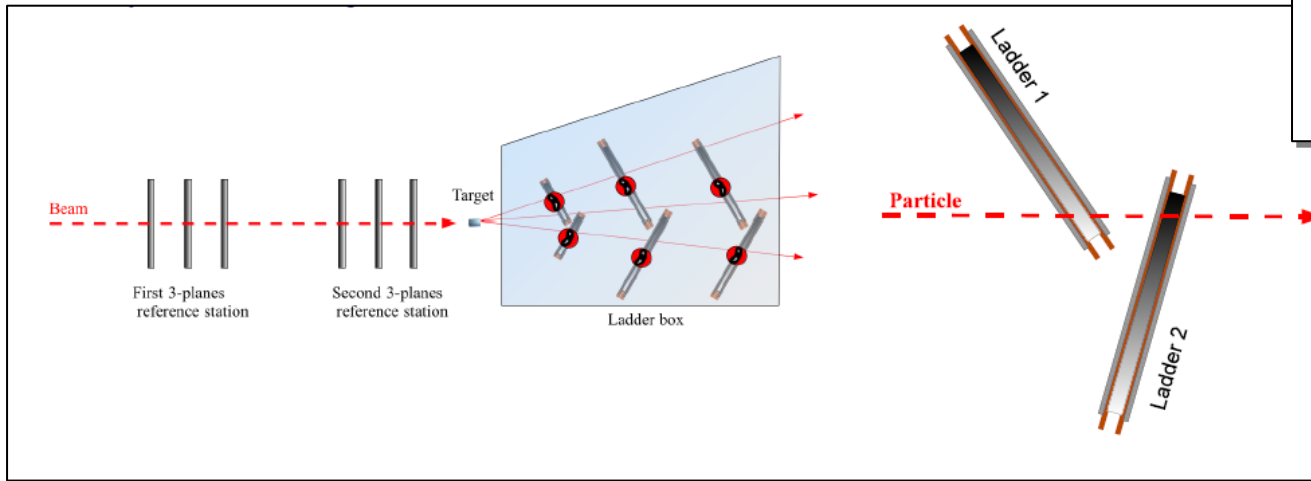
First data taking in 2013

First vertex detector equipped with CMOS pixel sensors !

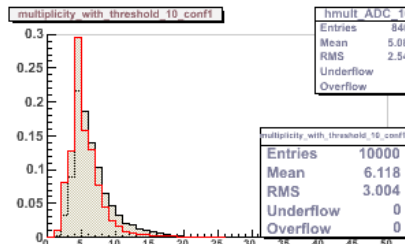
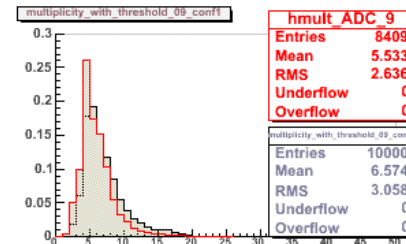
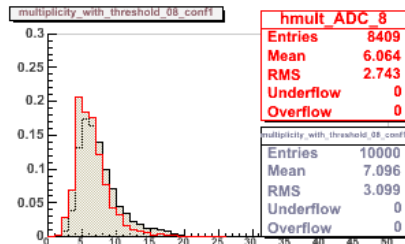
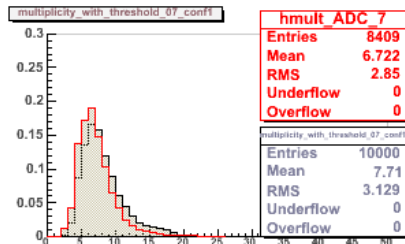
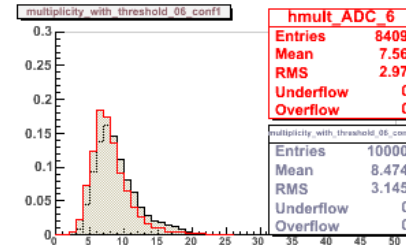
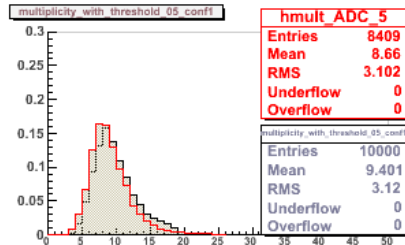
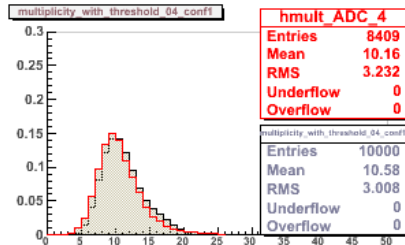
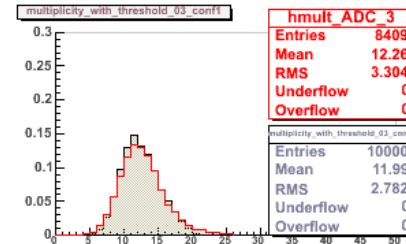
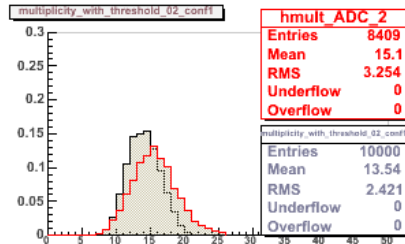
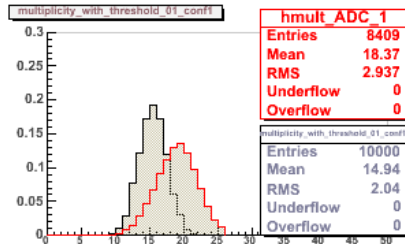


# AIDA

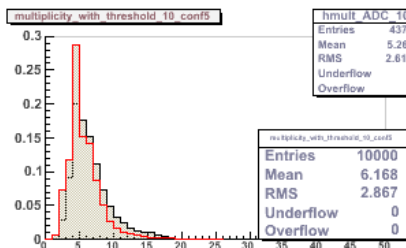
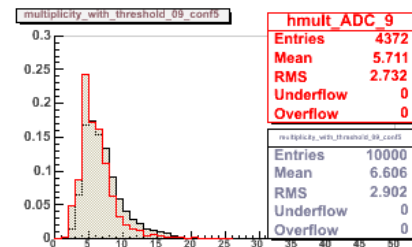
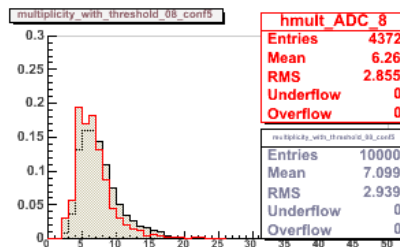
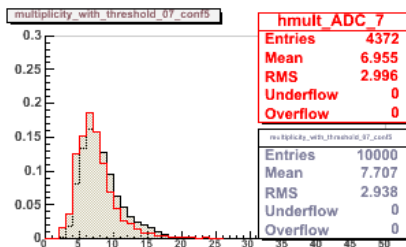
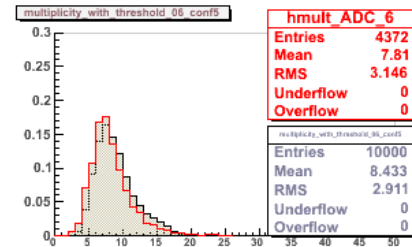
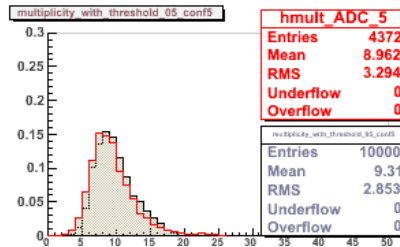
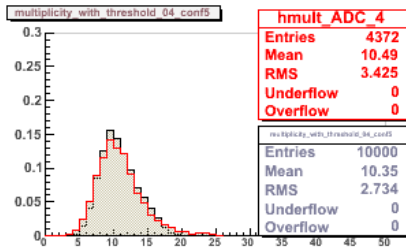
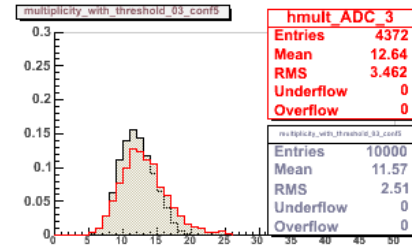
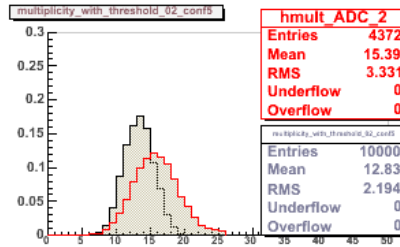
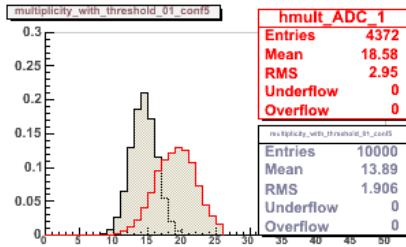
- AIDA (EU-FP7 WP9.3) test beam infrastructure (2014)
  - Large area beam tel. ( $\sim 6 \times 4$  cm<sup>2</sup>)
  - Alignment Investigation Device (AID)
    - Reproduce a VTX detector sector
    - Double sided ladders mounted on precise adjustable stages
  - Thermo-mechanical studies



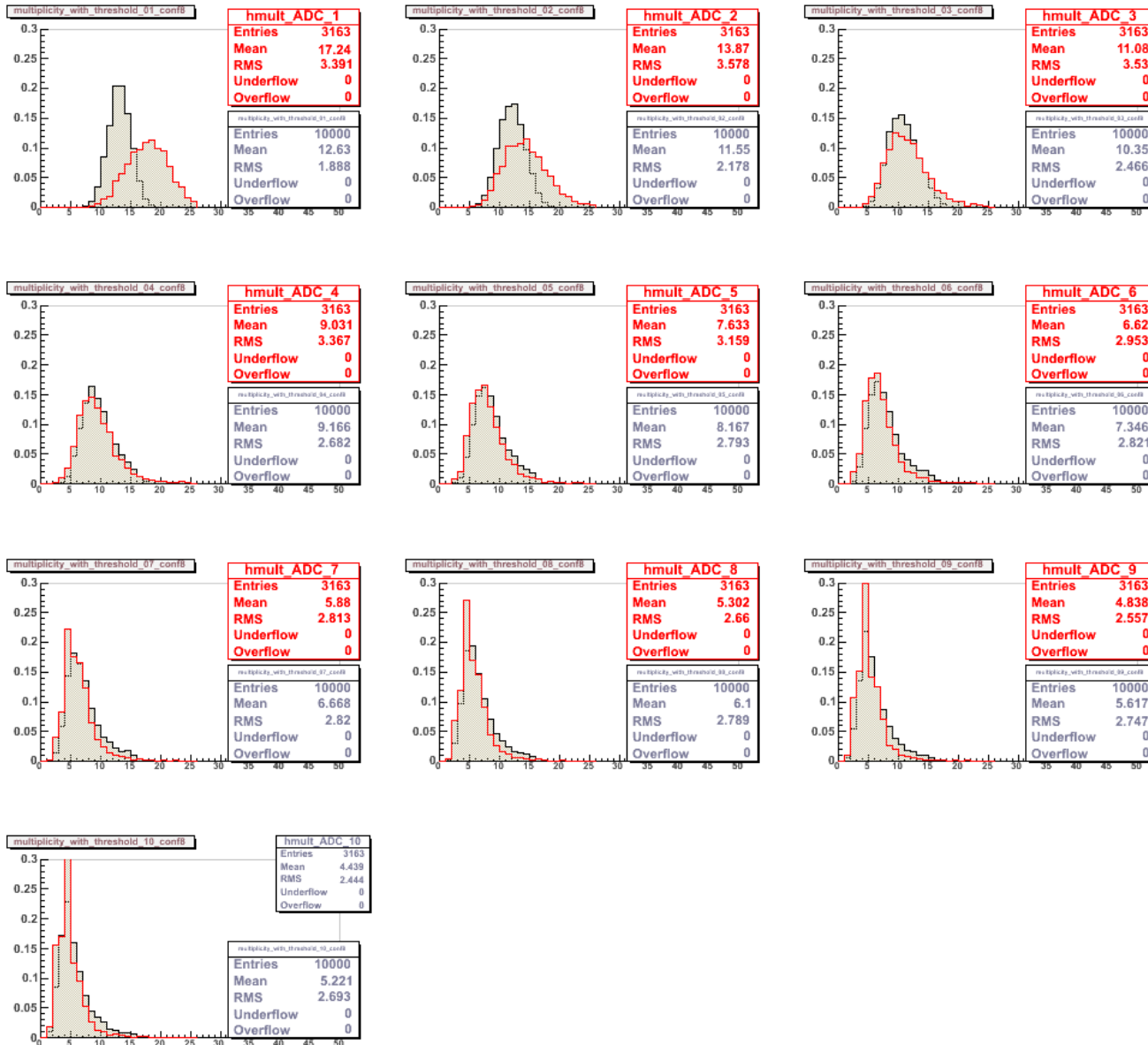
# 10 um pitch



# 20 um pitch



# 30 um pitch



# 40 um pitch

